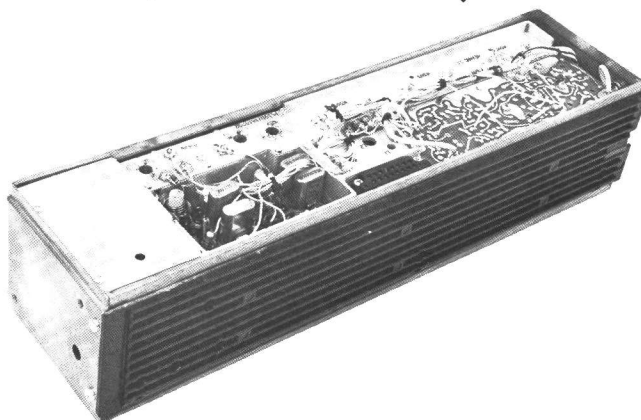


# MASTR

## Progress Line

**132-174 MHz RECEIVER MODELS 4ER41C22-33  
& 4ER41E22-33 (Includes Options 7341-7344)**



### SPECIFICATIONS \*

FCC Filing Designation

#### ER-41-C & E

Frequency Range

132-174 MHz

Audio Output

5 watts at less than 5% distortion

Sensitivity

12-dB SINAD (EIA Method)  
20-dB Quieting Method

0.20  $\mu$ V  
0.30  $\mu$ V

Selectivity

EIA Two-Signal Method  
20-dB Quieting Method

-90 dB (adjacent channel, 30 kHz channels)  
-100 dB at  $\pm 15$  kHz

Spurious Response

-94 dB

First Oscillator Stability

Type ER-41-C  
Type ER-41-E

$\pm .0005\%$  ( $-30^{\circ}\text{C}$  to  $+60^{\circ}\text{C}$ )  
 $\pm .0002\%$  ( $-30^{\circ}\text{C}$  to  $+60^{\circ}\text{C}$ )

Modulation Acceptance

$\pm 7$  kHz (narrow-band)

Squelch Sensitivity

Critical Squelch  
Maximum Squelch

0.15  $\mu$ V  
Greater than 20-dB quieting (less than  
1.5  $\mu$ V)

-75 dB

Intermodulation (EIA)

0.4%

Maximum Frequency Separation

Frequency Response

+1 and -8 dB of a standard 6-dB per  
octave de-emphasis curve from 300 to  
3000 Hz (1000-Hz reference)

\*These specifications are intended primarily for the use of the serviceman. Refer to the appropriate Specification Sheet for the complete specifications.

Maintenance Manual LBI-4034B  
DF-1094

**ER-41-C & E NOISE BLKR**

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### WARNING

No one should be permitted to handle any portion of the equipment that is supplied with high voltage; or to connect any external apparatus to the units while the units are supplied with power. KEEP AWAY FROM LIVE CIRCUITS.

## DESCRIPTION

General Electric MASTR Progress Line Receiver Types ER-41-C and ER-41-E are double conversion, superheterodyne FM receivers designed for operation on the 132—174 megahertz band. The Type ER-41-C receivers contain a standard crystal oscillator board with a frequency stability of  $\pm 0.0005\%$ . The Type ER-41-E receivers contain an optional Integrated Circuit Oscillator Module (ICOM) with a frequency stability of  $\pm 0.0002\%$ .

The receiver is of single-unit construction and is completely housed in an aluminum casting for maximum shielding and rigidity. The top compartment of the casting contains the RF, oscillator, converter, 1st IF amplifier and noise blanker. The bottom portion of the casting contains the IF audio and squelch board, and the optional Channel Guard board.

## CIRCUIT ANALYSIS

The MASTR Progress Line Receiver is completely transistorized, using silicon

transistors throughout for added reliability. Input leads to the receiver are individually filtered by the 20-pin feed-through by-pass connector J443. A regulated +10 volts is used for all receiver stages except the audio PA stage which operates from the 12-volt system supply.

Centralized metering jack J442 is provided for use with General Electric Test Set Models 4EX3A10 or 4EX8K10, 11 for ease of alignment and servicing. The Test Set meters the noise blanker, oscillator, multiplier, and limiter stages as well as the discriminator, and regulated 10 volts.

### RF PREAMPLIFIER (Part of Noise Blanker Board (A323/A324))

The RF Preamplifier Q12 uses a Dual Gate Field-Effect Transistor (FET) as the active device, and provides approximately dB of gain. RF from the antenna is coupled from J441 through the primary of T5 to Gate 1 of Preamplifier Q12. The amplified output signal at the Drain terminal of Q12 is coupled through cable W442 to the input of the 5-helical resonators (L301/L302 through L309/310).

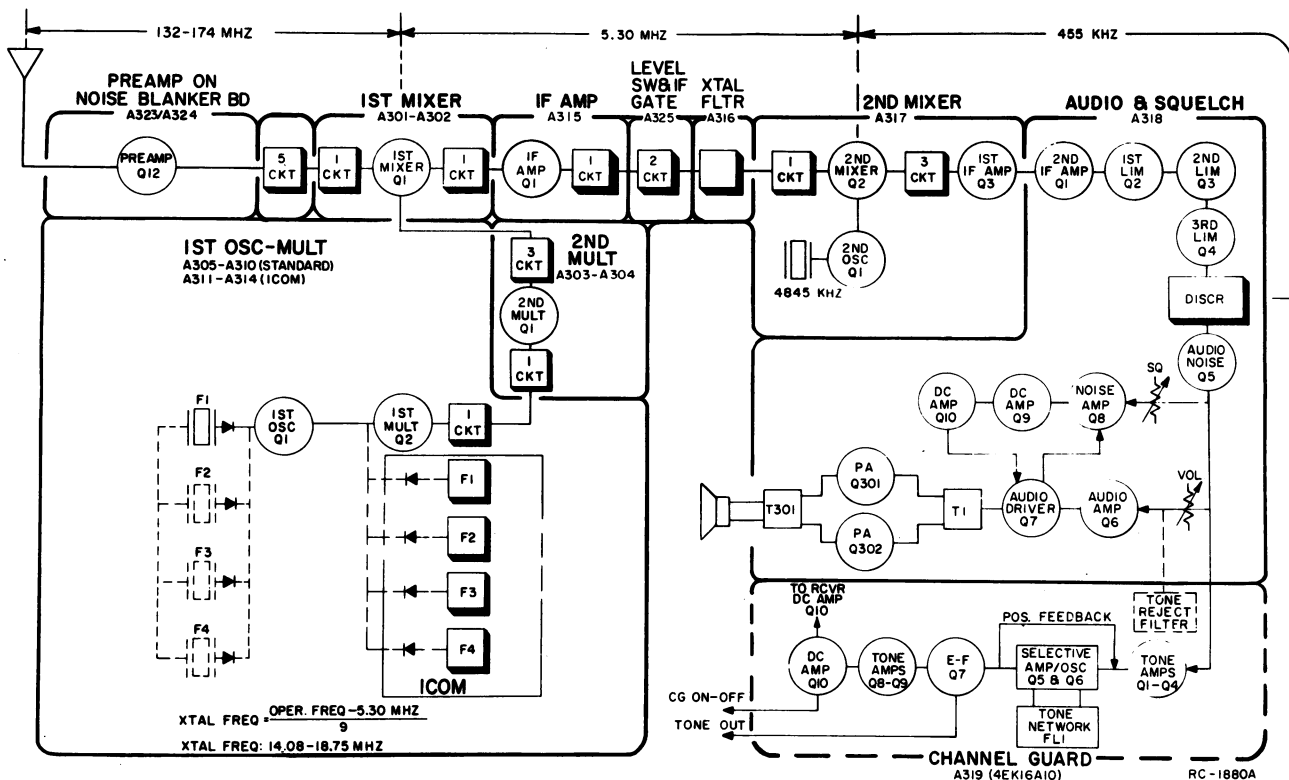


Figure 1 - Receiver Block Diagram

**NOTE**

In areas with high intermodulation interference and low receiver sensitivity requirements, the pre-amplifier may be disabled in the following manner. Remove Q12 and connect a 10-pf capacitor (GE Part No. 5496218-P10) between the Gate 1 and the "drain" points on the printed wiring board.

**HELICAL RESONATORS**

The five helical resonators (L301/L302 through L309/L310) provide additional RF selectivity of the signal from the amplifier. The tap on L301/L302 is positioned to provide the proper impedance match to the preamplifier. The output of the helical resonators is coupled through C3 to the 1st Mixer Assembly.

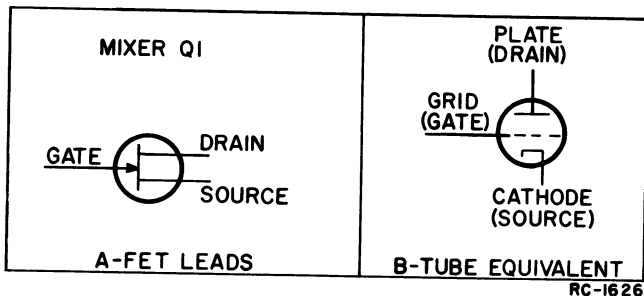


Figure 2 - FET Nomenclature

**STANDARD OSCILLATOR/MULTIPLIER (A305-A310)**

The receiver 1st oscillator operates in a transistorized Colpitts oscillator circuit. The oscillator crystal operates in a fundamental mode at a frequency of approximately 13 to 18 megahertz. The crystal is cut to provide temperature compensation at the high end of the temperature range and is thermistor compensated at low temperatures. This provides  $\pm 0.0005\%$  frequency stability as soon as the receiver is energized--without the warm-up time required by crystal ovens or warmers.

In single frequency receivers, bias for the oscillator transistor is obtained by a jumper from H1 to H2 on the oscillator board.

In multi-frequency receivers, a diode is connected in series with the crystal, and up to three additional crystal circuits can be added. The 10-volt jumper is removed

and the proper frequency is selected by switching the desired crystal circuit to +10 volts by means of a frequency selector switch on the control unit.

Switching the +10 volts to the crystal circuit forward biases the diode and reduces its impedance. This applies the crystal frequency to the base of oscillator transistor Q1. Feedback for the oscillator is developed across C21. The output is coupled to the base of 1st multiplier Q2.

The output of the 1st multiplier (triplier Q2) is transformer-coupled (T1/T2) to the 2nd multiplier assembly. The 1st multiplier tank is tuned to three times the crystal frequency, and is metered at centralized metering jack J442-4 through metering network CR5, R16, R5 and C33.

**OSCILLATOR/MULTIPLIER BOARD WITH ICOM (A311-A314)**

Oscillator/Multiplier Boards A311 thru A314 use ICOM Module Model 4EG26A11. The ICOM Module consists of a crystal controlled Colpitts oscillator, a voltage regulator and a buffer output stage. The entire module (including crystal) is enclosed in a dust-proof aluminum can, with the ICOM frequency and the receiver operating frequency printed on the top. Access to the oscillator trimmer is obtained by prying off the plastic GE decal on the top of the can.

The oscillator frequency is temperature-compensated at both ends of the temperature range to provide instant frequency compensation, with a frequency stability of  $\pm 0.0002\%$  without crystal ovens or warmers.

In single-frequency receivers, +10 volts for operating the ICOM is obtained by a jumper from H1 to H2. With the ICOM operating, diode CR1 is forward biased and the oscillator output is applied to 1st multiplier Q2.

The output of the 1st multiplier (triplier Q2) is transformer-coupled (T1/T2) to the 2nd multiplier assembly. The 1st multiplier tank is tuned to three times the crystal frequency, and is metered at centralized metering jack J442-4 through metering network CR5, R16, R5 and C33.

In multi-frequency receivers, up to three additional ICOM modules can be plugged into the board. The 10-volt jumper is removed and the proper frequency is selected by switching the desired ICOM to +10 volts by means of a frequency selector switch on the control unit.

**CAUTION**

All ICOM modules are individually compensated at the factory, and cannot be repaired in the field. Any attempt to remove the ICOM cover will void the warranty.

**2ND MULTIPLIER (A303/A304)**

The 1st multiplier output is transformer-coupled through A303-T1/T2 to the base of 2nd multiplier A303-Q1. Following the 2nd multiplier are two resonant L-C circuits and a helical resonator tuned to nine times the crystal frequency. The output is taken from a tap on L311/L312 and applied to the 1st mixer.

**1ST MIXER (A301/A302)**

The 1st mixer uses a Field-Effect Transistor (FET) as the active device (Fig. 2).

The FET has several advantages over a conventional transistor, including a high input impedance, high power gain, and an output that is relatively free of harmonics (low in intermodulation products).

In mixer A301/A302, RF from the helical resonators is applied to the gate of Q1, and injection voltage from the 2nd multiplier is applied to the source. The mixer output is taken from the drain with the output tuned to the 5.3 MHz high IF frequency.

**HI IF AMPLIFIER (A315) AND CRYSTAL FILTER (A316)**

A series-resonant circuit (A301/A302-L3 and A315-C1) couples the mixer output to the emitter of the high IF amplifier A315-Q1. The transistor is connected as a grounded-base amplifier which provides a low impedance for the mixer input. The amplifier output is coupled through transformer T1 and circuits of the Level Switch & IF Gate A325 to the crystal filter.

The highly-selective crystal filter (A316) provides the major selectivity for the receiver. The output of the filter is coupled through impedance-matching transformer A317-T1 to the base of the 2nd mixer.

**2ND OSCILLATOR, 2ND MIXER AND 1ST LO IF AMPLIFIER (A317)**

A317-Q2 operates in a Colpitts oscillator circuit, with feedback supplied through C4. The oscillator low-side injection voltage (4845 kHz) is applied to the base of the 2nd mixer.

The High IF signal from the filter and the injection voltage from the 2nd oscillator is applied to the base of 2nd mixer Q2.

The 445-kHz mixer output is applied to three tuned low IF circuits, L1, L2 and L3. These tuned circuits are required for shaping the nose of the IF waveform, and for rejecting any undesired output frequencies from the 2nd mixer.

The low IF signal is applied to the base of 1st low IF amplifier Q317-Q3. The output of A317-Q3 is R-C coupled to the base of the 2nd low IF amplifier.

**2ND LOW IF AMPLIFIER AND LIMITERS (A318)**

Additional amplification of the low IF signal going to the limiter stages is provided by 2nd low IF amplifier A318-Q1. This stage is metered at J442-2 through a metering network consisting of C19, CR3 and R25.

Following the 2nd low IF amplifier are three R-C coupled limiter stages (A316-Q2, -Q3 and -Q4). The 1st limiter is metered at J442-3 through metering network C20, CR4 and R26.

**DISCRIMINATOR (A318)**

The limiter output is applied to a Foster-Seely type discriminator, where diodes CR1 and CR2 rectify the 455-kHz signal to recover the audio. The discriminator is metered at J442-10 through metering network C16 and R23.

**AUDIO - NOISE AMPLIFIER (A318)**

The discriminator output is coupled through a low-pass filter (C16, C18, R21 and R22) to the base of audio-noise amplifier Q5. The filter removes any 455-kHz signal remaining in the discriminator output. Q5 operates as an emitter-follower to match the discriminator impedance to the VOLUME control, SQUELCH control, and Channel Guard input. The stage also provides power gain.

**AUDIO AMPLIFIERS (A318)**

Any audio present in the incoming signal is coupled from the emitter of Q5 through the VOLUME control and a de-emphasis network to the base of audio amplifier Q6. The de-emphasis network consists of C22, C23, C24, R30 and R31.

Audio driver Q7 follows the audio amplifier. The output of Q7 is coupled through transformer T1 to provide phase inversion for the push-pull audio PA stage.

Q301 and Q302 operate as a push-pull, Class AB audio PA stage. The PA output is coupled through audio transformer T301 to the loudspeaker. The yellow and white tertiary windings of T301 supply balanced feedback to the collector of Q7 minimize distortion.

Base bias for the PA stage and the elimination of crossover distortion is controlled by bias adjust potentiometer R43. The potentiometer is set at the factory as shown in STEP 1 of the receiver Test Procedure.

#### NOTE

Do not adjust bias adjust potentiometer R43 unless PA transistors Q301 and Q302 have been replaced.

Audio high and low are also present at centralized metering jack J442, and can be used as shown in STEP 1 of the receiver Test Procedure. The output stage provides 5 Watts at less than 5% distortion into a 3.5-ohm load at the receiver output terminals (3.2-ohm load at the Control Unit).

#### SQUELCH (A318)

Noise from the audio-noise amplifier operates the squelch circuit. With no carrier present in the receiver, this noise is coupled to the base of noise amplifier Q8 through a high-pass filter which attenuates frequencies below 3 kHz. The filter consists of C30, C31 and R45, as well as C34 and L3 in the collector circuit of Q8. The gain of Q8 is determined by the Squelch control, which varies the bias on the base of Q8. Thermistor RT2 keeps the critical squelch constant over wide variations in temperature.

The output of noise amplifier Q8 is rectified by diodes CR5 and CR6, and filtered by C36 and C37 to produce a negative DC voltage. This DC voltage is applied to the base of DC amplifier Q9, turning it off. When turned off, the collector voltage of Q9 rises to approximately 8 Volts, turning on DC amplifier Q10. When conducting, the collector voltage of Q10 drops to almost ground potential, which removes the base bias to audio amplifier Q6 and audio driver Q7, turning them off.

When the receiver is quieted by a signal (unsquelches), the noise in the receiver is reduced, turning DC amplifier Q9 on and DC amplifier Q10 off. This allows the audio stages to conduct so that sound is heard in the speaker. A network composed of C38, CR7 and R62 slows down the switching action of Q10, preventing an obnoxious "thump" from being heard in the speaker.

Resistor R53 connects from the emitter of audio driver Q7 to the emitter of noise amplifier Q8, providing a hysteresis loop in the squelch circuit. When a weak signal opens the squelch, the signal level may be reduced by 4 to 6 dB without the squelch

closing. This limits squelch "flutter" or "picket-fence" operation.

With audio driver Q7 conducting, a positive voltage through R53 helps to reduce the gain of noise amplifier Q8. This positive feedback provides a quick, positive switching action in the squelch circuit. When the receiver squelches, audio driver Q7 turns off and its emitter potential drops to zero. This reduces the DC feedback through R53 to the emitter of noise amplifier Q8. Reducing the feedback causes Q8 to conduct harder, turning the audio stages off quickly.

Keying the transmitter removes the +10 Volts from J19, turning off DC amplifier Q9 and turning on Q10 to mute the receiver.

#### NOISE BLANKER

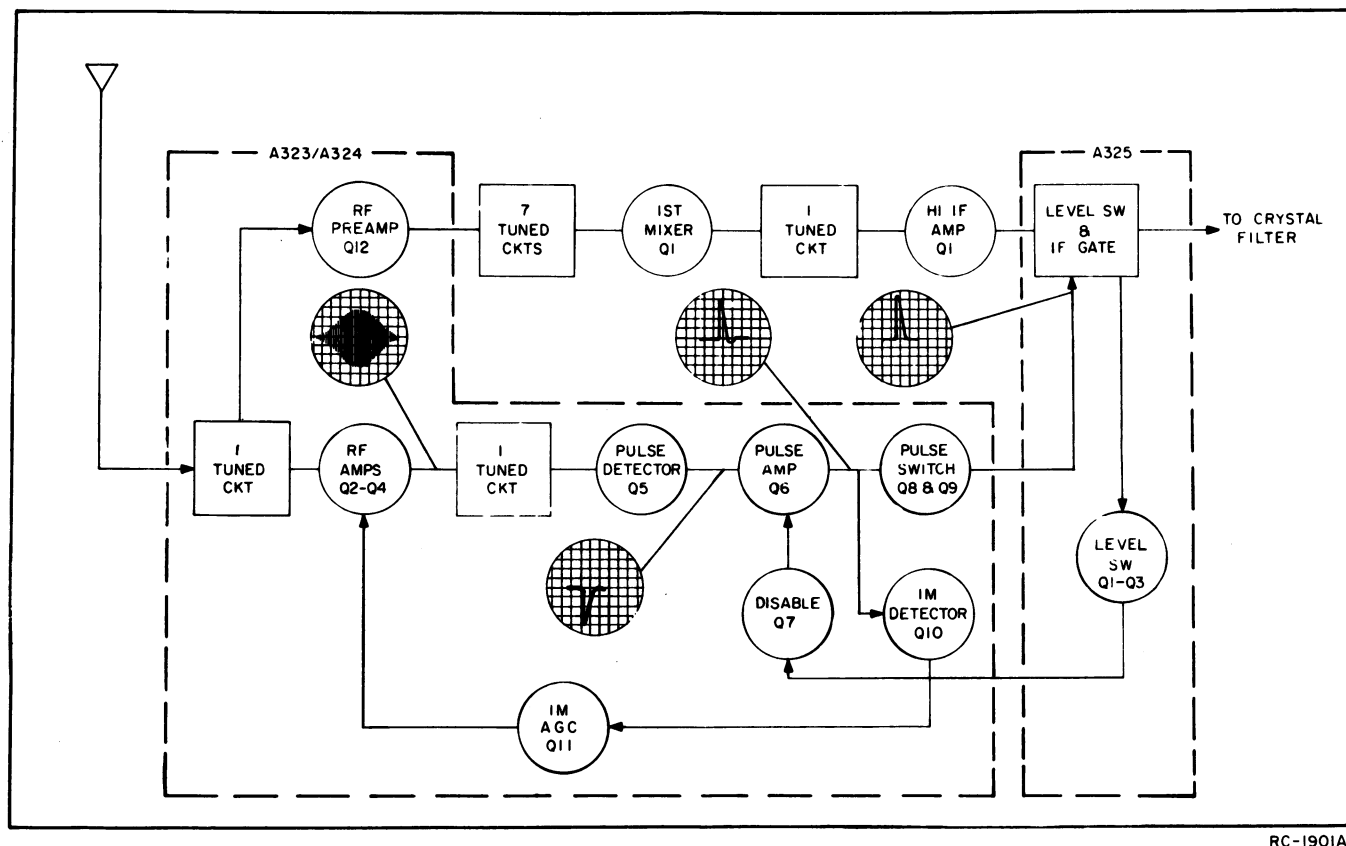
The General Electric Noise Blanker reduces or eliminates interference from automobile ignition noise, corona and other impulse noise sources. It is constructed on two separate printed circuit boards; a Noise Blanker Board A323/A324 and a Level Switch & IF Gate Board A325 (Refer to Figure 3). The design of the blanker gives it the ability to blank impulse noise while suppressing the effects of intermodulation, and to automatically shut off when the RF signal strength is strong enough to override noise interference.

The Noise Blanker will work when a Dual Front End is used, because the IF output of the Dual Front End is connected to the input of the Level Switch & IF Gate Board A325.

#### Operation

RF signals and noise pulses from the antenna are applied simultaneously to the receiver RF Preamplifier Q12 and the 1st RF Amplifier Q2 on the noise blanker board. Three tuned RF stages (Q2-Q4) in the blanker provide approximately 45 dB of gain when the automatic gain control (AGC) circuit is not operating. The RF amplifier stages are tuneable between 130—150 MHz and are set on frequency according to the table in the Receiver Alignment Procedure. The 130—150 MHz tuning range was chosen because the low two-way radio activity in this part of the spectrum allows sampling of noise with minimum interference from intermodulation and blanker desensitization. A metering network consisting of C28, CR2 and R18 permits the blanker to be metered at pin 11 of centralized metering jack J442.

The signal from the 3rd RF Amplifier Q4 is coupled through T9 to the base of pulse detector Q5. This stage is an amplitude detector that is sensitive to impulse or sinusoidal signals and detects noise pulses if the RF signal at the antenna in-



RC-1901A

Figure 3 - Noise Blanker Block Diagram

put has an intensity of 5.0 microvolts or more. Q5 is normally biased by R16, R17 and CR1 so that it is barely conducting. When the noise pulse is applied to its base, Q5 conducts heavily. This results in a negative pulse at the output (collector) of Q5.

Following Q5 is a low-pass RF filter consisting of C33 and L5 which provides an output to the base of Pulse Amplifier Q6. Q6 amplifies the pulse and provides outputs for Pulse Switch Q8 & Q9 and Intermodulation Detector Q10. Operation of the Pulse Amplifier (Q6) is disabled when Q7 is turned on by a signal from the High Level Cut-Off Circuit or when J443-15 is jumpered to system negative (J443-13).

The signal from Q6 operates Pulse Switch Q8 & Q9. The resulting blanking pulses are applied to the anode of CR1, CR2, and CR3 on the Level Switch & IF Gate (A325) turning the diodes on. While a blanking pulse is applied to the diodes, the RF from the Hi IF Amplifier is attenuated 55 dB to provide the blanking function. The pulses from the switch have a width of approximately 3 microseconds with a minimum interval of 3 microseconds between pulses. Therefore, the blanker will operate on noise with frequencies up to 150 kHz.

The automatic gain control circuit controls the gain of the RF stages and only operates in the presence of close-spaced intermodulation. A portion of the signal from Pulse Amplifier Q6 is applied to the base of Intermodulation Detector Q10. Since intermodulation is sinusoidal in nature, the negative going part of the sine wave is detected and used to control the IM AGC transistor Q11. (Impulse noise is primarily positive, and does not operate the automatic gain control circuit). Once the intermodulation is detected, the negative output from Q10 causes Q11 to conduct more. This reduces the positive voltage on the base of 2nd RF Amplifier Q3, reducing the RF gain to the point that intermodulation will not cause blanking. While the AGC is operating, the blanker sensitivity is reduced. However, it still blanks impulse noise and will continue to do so unless intermodulation becomes severe enough to completely reduce RF gain.

A High Level Cut-Off Circuit (A325-Q1 Q2 & Q3) is used to disable the blanker when a high level RF signal that is not subject to noise interference is received. A portion of the Hi IF Amplifier output is amplified by Q1 & Q2 and then detected by CR4 & CR5. The resultant positive voltage turns on transistor Q3. When Q3 conducts, its collector potential becomes essentially

-10 Volts (System Negative). This voltage is applied to the base of Q7, turning Q7 on and disabling noise blanker operation.

#### CHANNEL GUARD

Channel Guard Board Model 4EK16A10 is a fully transistorized encoder-decoder for use the MASTR Professional Series mobile and station combinations. The tone frequencies are controlled by plug-in tone networks that are made with precision components for excellent stability and reliability. The tone frequencies range from 71.9 to 203.5 Hz.

#### Encoder (A319)

Keying the transmitter removes the receiver mute +10 Volts, and forward biases feedback control diode CR5, causing it to conduct. When conducting, the diode shunts R39 which reduces the impedance of the positive feedback loop (R39, R35 and C19). This provides the necessary gain to the base of Q5 to permit oscillation.

The encoder tone is provided by selective amp-oscillator transistors Q5 and Q6 which oscillate at a frequency determined by the tone network. Negative feedback applied through the tone network to the base of Q5 prevents any gain in the stage except at the desired encode frequency.

Starting network R45, C21, C22 and CR6 provide an extremely fast starting time for the encoder tone. Keying the transmitter removes the receiver mute +10 Volts, causing a pulse to be applied to the base of Q6 to quickly start the oscillator. Thermistor-resistor combination R32 and RT1 provides temperature compensation for the oscillator output. Limiter diodes CR3 and CR4 keep the tone amplitude constant.

Emitter-follower Q7 follows the oscillator circuit. The encoder tone is taken from the emitter of Q7 and applied to an active low-pass filter (G101) on the transmitter.

#### Decoder (A319)

The decoder function is designed to eliminate all calls that are not tone coded for the Channel Guard frequency. As long as the CHANNEL GUARD-OFF switch on the control unit is left in the CHANNEL GUARD position, all signals are locked out except those from transmitters that are continuously tone coded for positive identification by the receiver.

Placing the CHANNEL GUARD-OFF switch in the OFF position instantly disables the Channel Guard operation so that all calls on the channel can be heard. When the hook-switch option is used, lifting the

microphone from its hanger disables the Channel Guard circuit.

Audio, tone and noise are taken from the emitter of the receiver audio-noise amplifier A318-Q5 and is fed through A319-J1 to four tone amplifier and bandpass filter circuits. The filters remove the audio and high-frequency noise from the signal, and the tone amplifiers provide sufficient gain to insure clipping by limiter diodes CR1 and CR2. The clipping action eliminates variation in the squelch performance due to changes in tone deviation. The signal is then applied to selective amplifiers Q5 and Q6 which amplify only the tone determined by the tone network.

The output of the selective amplifier is applied through emitter-follower Q7 to the high gain, broad-band tone amplifiers Q8 and Q9. The output of Q9 is rectified by detector diodes CR7 and CR8, and the resulting negative DC voltage controls the squelch gate. Q8 is normally biased for low gain. Then the tone is detected by CR7 and CR8, feedback is provided through R54 to quickly change the bias on Q8 for full gain. This ensures a more positive "unsquelching" action.

Squelch gate diode CR9 is normally forward biased by a positive DC voltage (approximately 1.5 Volts) fed through R58. The forward bias causes CR9 to conduct, feeding a DC voltage to the base of DC amplifier A318-Q10 in the receiver. This removes the bias on the receiver audio stages and holds them off.

When the proper tone is applied to the decoder, the negative DC voltage from the detector diodes back-biases squelch gate diode CR9 and cuts off the positive bias to the receiver DC amplifier A318-Q10. However, the receiver noise squelch circuit continues to operate until a carrier quiets the receiver.

Placing the CHANNEL GUARD - OFF switch in the OFF position (or removing the microphone from its hookswitch) removes the ground to the base of the decoder DC switch (Q10), causing it to conduct. This back-biases squelch control diode CR9 and cuts off the positive bias to the receiver DC amplifier (A318-Q10). The receiver noise squelch circuit continues to operate until a carrier quiets the receiver.

A tone rejection filter connected in parallel with A318-J2 (in the receiver bypasses any incoming tone to ground. This attenuates the tone level reaching the receiver audio circuits. The filter is composed of C26, C27, C28, C29, L1 and R59.

An optional tone reject filter (A320) that is identical to the filter described above is available for use in two-way radios with transmitter Channel Guard only.

# MAINTENANCE

## DISASSEMBLY

To service the receiver from the top—

- 1. Pull locking handle down and pull radio about one inch out of mounting frame.
- 2. Pry up cover at rear of receiver.
- 3. Slide cover back and lift off.

To service the receiver from the bottom—

- 1. Pull locking handle down. Pull radio out of mounting frame.
- 2. Remove screws in bottom cover. Pry up cover at back of receiver.
- 3. Slide cover back and lift off.

To remove the receiver from the system frame—

- 1. Loosen the two Phillips-head retaining screws in front casting (see Figure 4), and pull casting away from system frame.
- 2. Remove the four screws in the back cover.
- 3. Remove the two screws holding the receiver at each end of the system frame.
- 4. Disconnect the antenna jack and the 20-pin connector from the front of the receiver, and slide the unit out of the system frame.

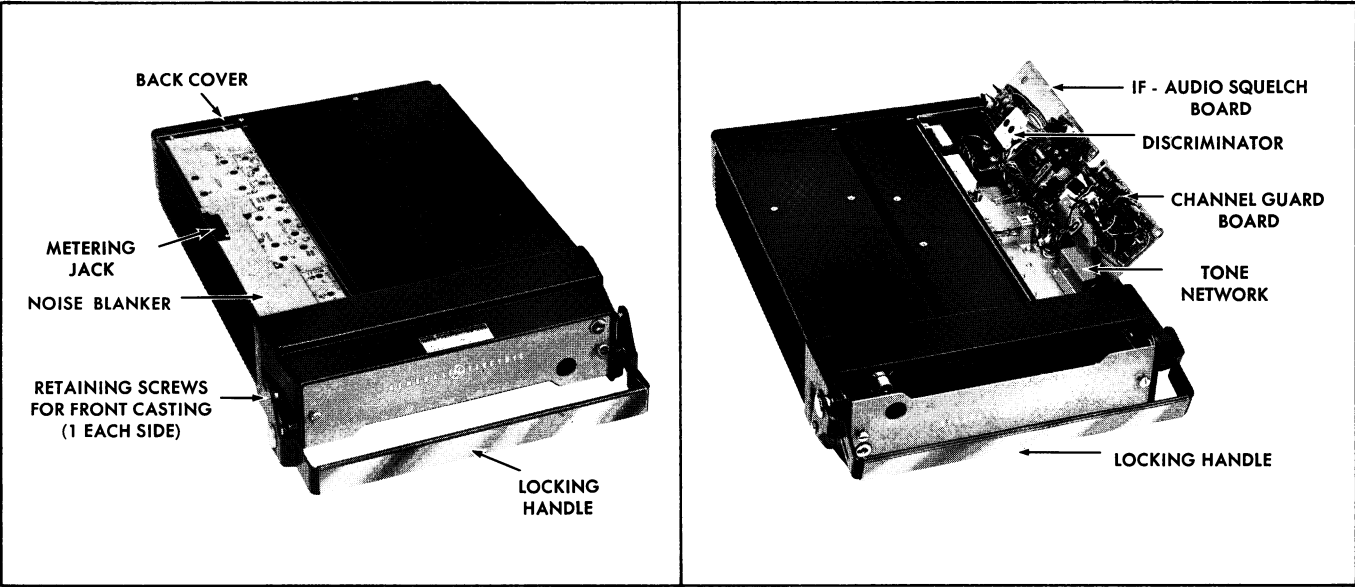


Figure 4 - Removing Top Cover

Figure 5 - Removing Bottom Cover

ICOM FREQUENCY ADJUSTMENT

Due to the high stability of the ICOM module, it is not recommended that zero discriminator be used as the indication for setting the oscillator frequency. Instead, measure the ICOM frequency as described in the following procedure.

EQUIPMENT REQUIRED:

- 1. Frequency Counter capable of measuring the 42 to 56.25 MHz frequency range. The counter should have an accuracy of 0.4 part-per million (PPM).
- 2. Coaxial cable with test loop as described in Figure 6.
- 3. Mercury thermometer.

PROCEDURE:

- 1. Check ICOM temperature by taping the mercury thermometer to the side of the ICOM.
- 2. Connect the coaxial cable to the frequency counter. Then place the 4-turn test loop over L1 on the 1st OSC/MULT board.
- 3. If the ICOM temperature is 80°F (±4°F) or 26.5°C (±2°C), the frequency indication of the counter should be 3 times the frequency stenciled on the ICOM case. Adjust the ICOM trimmer (if necessary) to obtain this frequency.
- 4. If the temperature is not within the 80°F (±4°F) or 26.5°C (±2°C) range, use the correction curves of Figure 7 for setting the ICOM frequency as follows:
  - a. Check the color dot beneath the GE emblem and select the matching curve to determine the correction factor in parts-per-million (PPM).
  - b. Multiply the frequency stenciled on the ICOM by 3 and then multiply this figure by the correction factor (from Figure 7) observing the sign (±) given to the correction factor.
  - c. The frequency measured at L1 should be 3 times the ICOM frequency ± the correction factor. Adjust the ICOM trimmer (if required) to obtain this frequency.

EXAMPLE

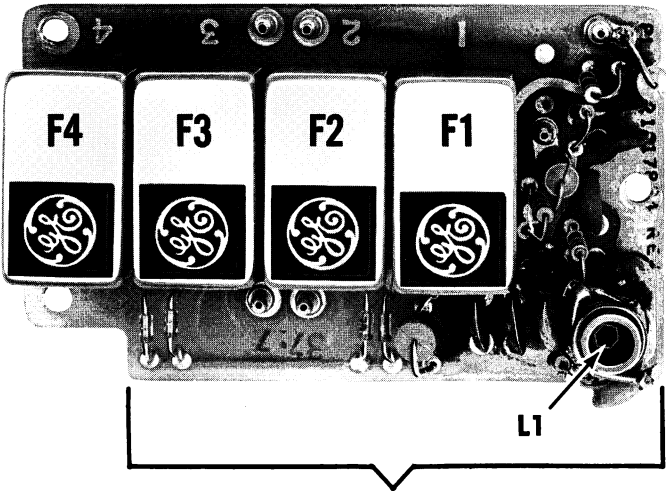
ICOM Frequency	-	16.948,148 MHz
ICOM Color Dot	-	Green
Ambient Temperature	-	35°C (95°F)
Correction Factor	-	-1.15 PPM

Multiply ICOM Frequency by 3; (16.948,148 MHz x 3 = 50.844,444 MHz)

Multiply preceding figure by correction factor; (50.844 MHz x -1.15 PPM = -58.47 hertz (or -58 hertz)

Set the frequency measured at L1 for 50.844,386 MHz;

50.844,444  
- 58  
50.844,386



1ST OSC MULT. (ER-41-E)

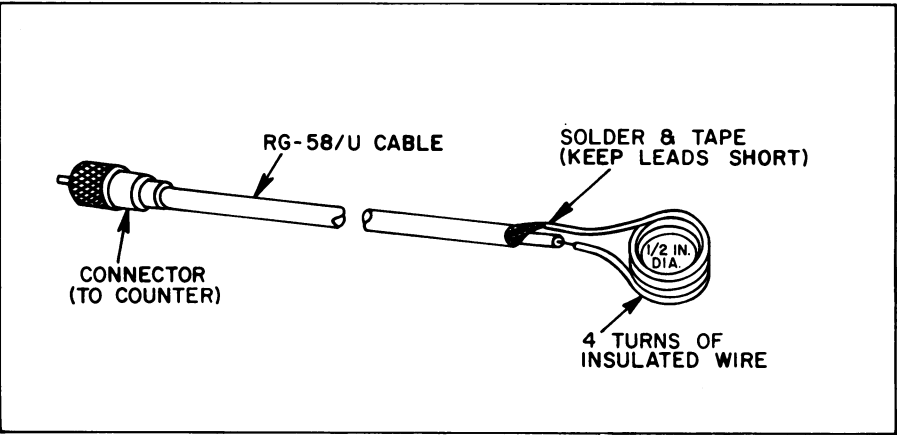


Figure 6 - Coaxial Cable and Test Loop RC-1779

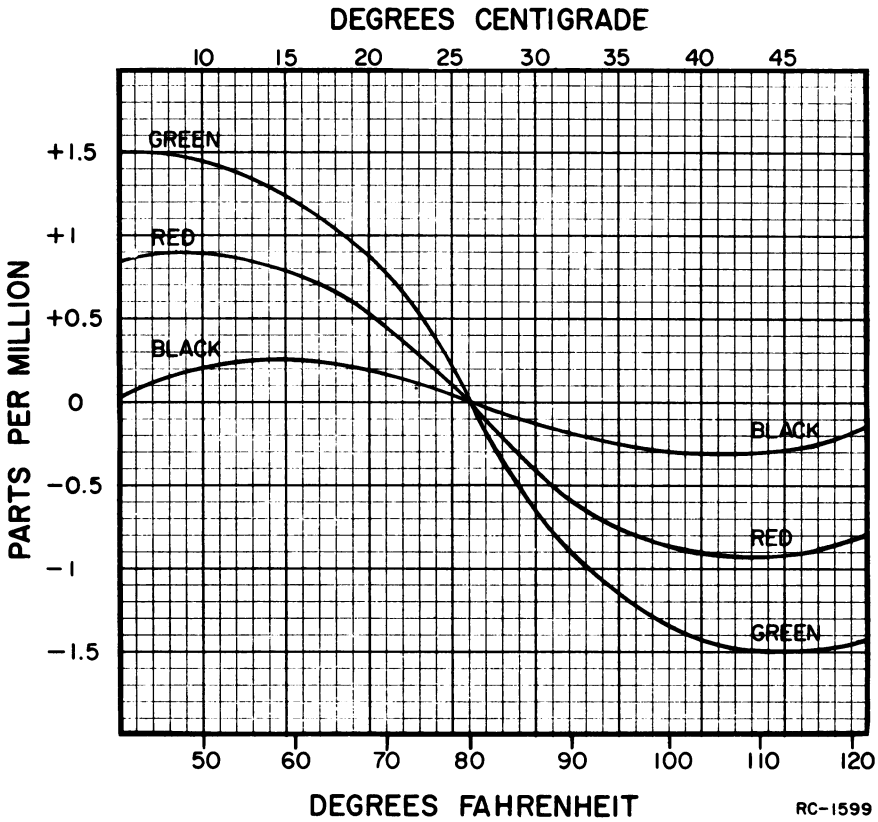


Figure 7 - ICOM Correction Curves

ADJUSTMENT PROCEDURE

ICOM ADJUSTMENT  
MODELS 4ER41E22-33



TEST PROCEDURES

These Test Procedures are designed to help you to service a receiver that is operating---but not properly.

The problems encountered could be low power, poor sensitivity, distortion, limiter not operating properly, and low gain. By following the sequence of test steps starting with Step 1, the defect can be quickly localized.

Once the defective stage is pin-pointed, refer to the "Service Check" listed to correct the problem. Additional corrective measures are included in the Troubleshooting Procedure. Before starting with the Receiver Test Procedures, be sure the receiver is tuned and aligned to the proper operating frequency.

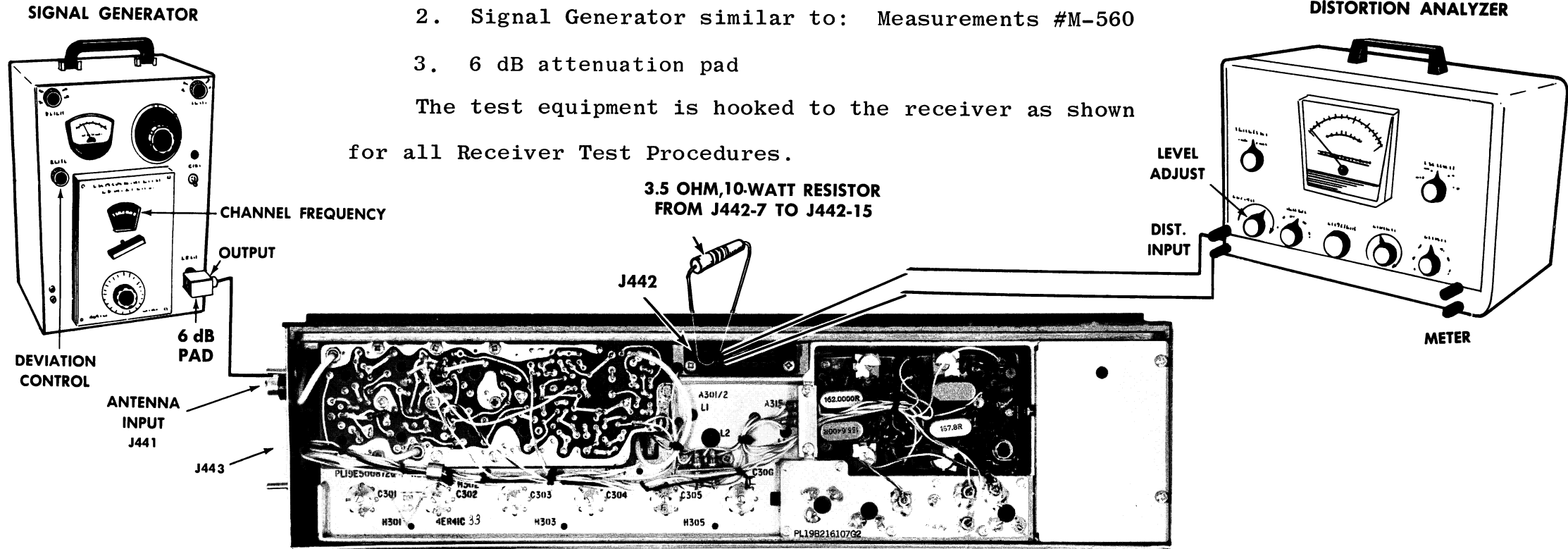
TEST EQUIPMENT REQUIRED

for test hookup shown:

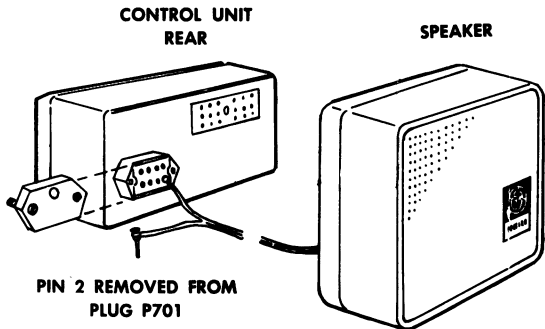
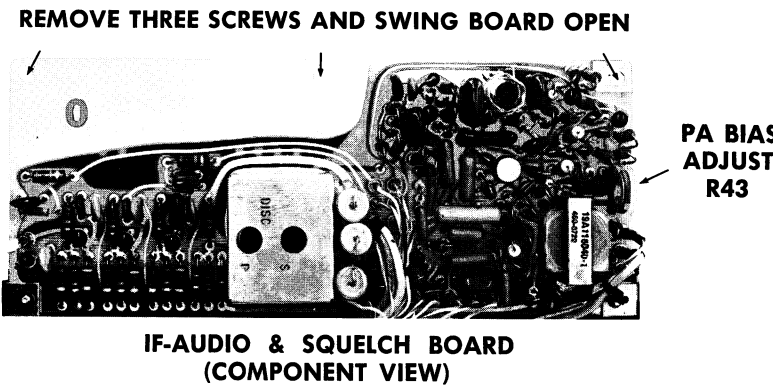
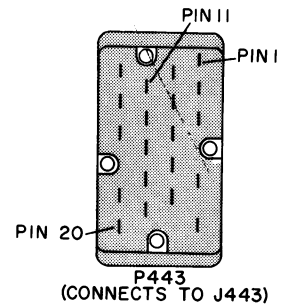
- 1. Distortion Analyzer similar to: Heath #1M-12
- 2. Signal Generator similar to: Measurements #M-560
- 3. 6 dB attenuation pad

The test equipment is hooked to the receiver as shown

for all Receiver Test Procedures.



COMPONENT TOP VIEW



STEP 1

AUDIO POWER OUTPUT AND DISTORTION

TEST PROCEDURE

Measure Audio Power Output as follows:

- A. Connect a 1,000-microvolt test signal modulated by 1,000 hertz  $\pm 3.0$  kHz deviation to the antenna jack J441.

- B. With Five-Watt Speaker:

Disconnect speaker lead pin from J701-2 (on rear of Control Unit).

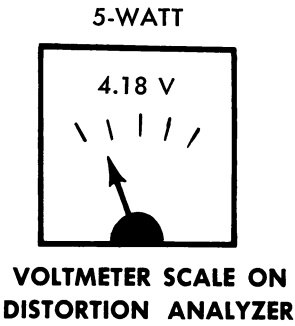
Connect a 3.5-ohm load resistor from J442-15 to J442-7. Connect the Distortion Analyzer input across the resistor as shown.

OR

With Handset:

Lift the handset off of the hookswitch. Connect the Distortion Analyzer input from J442-15 to J442-7.

- C. Set the VOLUME control for five-watt output (4.18 VRMS).
- D. Make distortion measurements according to manufacturer's instructions. Reading should be less than 5%.



SERVICE CHECK

If the distortion is more than 5%, or maximum audio output is less than five watts, make the following checks:

- E. Battery and regulator voltage---low voltage will cause distortion. (Refer to Receiver Schematic Diagram for voltages.)
- F. P.A. Bias Adjust (R43)-- Turn the SQUELCH control fully counterclockwise. Then connect a milliammeter in series with the +12 volt lead at P443-11. With no signal in, adjust R43 for a reading of approximately 20 milliamps. This adjustment should not be necessary unless an output transistor has been replaced.
- G. Audio Gain (Refer to Receiver Troubleshooting Procedure).
- H. Discriminator Alignment (Refer to Receiver Alignment on reverse side of page).

STEP 2

USABLE SENSITIVITY (12 db SINAD)

TEST PROCEDURE

Measure sensitivity of the receiver modulated at the standard test modulation as follows:

- A. Be sure Test Step 1 checks out properly.
- B. Reduce the Signal Generator output from setting in Test Step 1A.
- C. Adjust Distortion Analyzer LEVEL control for a +2 dB reading.
- D. Set CONTROL from LEVEL to DISTORTION reading. Repeat Steps 2B and 2C until difference in reading is 12 dB (+2 dB to -10 dB).
- E. The 12-dB difference (Signal plus Noise and Distortion to noise plus distortion ratio) is "usable" sensitivity level. Reading should be less than the rated 12 dB SINAD specification with audio output at least 2.5 watts (2.9 volts RMS across the 3.5-ohm receiver load).

SERVICE CHECK

If the sensitivity level is not within rated specifications, make the following checks:

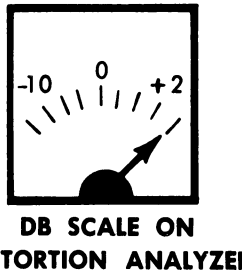
- F. Alignment of RF stages (Refer to RF Alignment in Receiver Alignment on reverse side of page).
- G. Gain measurements as shown on the Receiver Troubleshooting Procedure.

STEP 3

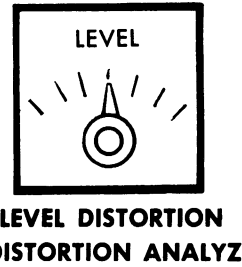
MODULATION ACCEPTANCE BANDWIDTH (IF BANDWIDTH)

TEST PROCEDURE

- A. Be sure Test Steps 1 and 2 check out properly.
- B. Set Signal Generator output for twice the microvolt reading obtained in Test Step 2D.
- C. Increase Signal Generator frequency deviation.
- D. Adjust LEVEL Control for +2 dB.



- E. Set CONTROL from LEVEL to DISTORTION reading. Repeat Steps 3C, 3D and 3E until difference between readings becomes 12 dB (from +2 dB to -10 dB).



- F. Deviation control reading for the 12-dB difference is the Modulation Acceptance Bandwidth of the receiver. It should be more than  $\pm 7$  kHz (but less than  $\pm 9$  kHz).

SERVICE CHECK

If the Modulation Acceptance Bandwidth test does not indicate the proper width, make gain measurements as shown on the Receiver Troubleshooting Procedure.

TROUBLESHOOTING PROCEDURE

Before starting the Noise Blanker troubleshooting procedure, make sure the receiver is operating properly. Align the Noise Blanker as described on the ALIGNMENT PROCEDURE Sheet. Then make the following Troubleshooting checks:

STEP 1—PERFORMANCE CHECK

Equipment Required:

RF Signal Generator coupled through a 6 dB pad.

Pulse Generator with repetition rate and level controls (similar to General Electric Model 4EX4A10)

AC VTVM

Procedure:

1. Connect Pulse Generator and RF Signal Generator to receiver antenna jack through a T-connector and connect VTVM to receiver output as shown in Figure 1.

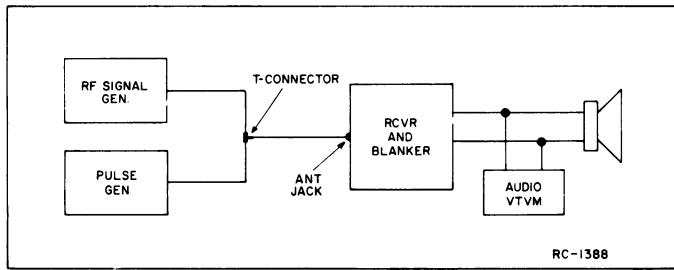


Figure 1 - Equipment Connection Diagram

2. Apply an unmodulated RF Signal and check the 20 dB quieting sensitivity of the receiver. (Measure with Model 4EX4A10 Pulse Generator connected but turned off).
3. Disable pulse section of the noise blanker by connecting a jumper between J443-15 and J443-13 (system negative).
4. Set the pulse generator (Model 4EX4A10) repetition rate to 10 kHz and adjust the output level control on pulse generator until receiver sensitivity is degraded as much as possible (approximately 45 dB).
5. Remove the jumper between J443-15 and J443-13. The receiver sensitivity should restore to within 5 dB of 20 dB quieting level obtained in step 2 above.

STEP 2—QUICK CHECKS

Equipment Required:

Audio Voltmeter (VTVM)  
Audio Oscillator (sine wave)

SYMPTOMS	PROCEDURE
No regulated 10-Volts	Check the 12-volt supply. Then check regulator circuit. (Refer to troubleshooting procedure for power supply.)
Partial or no blanking	<ol style="list-style-type: none"><li>a. Check voltage ratios (STEP 4).</li><li>b. Check waveforms (STEP 3).</li><li>c. Check IF Gate as follows: Connect signal generator to Antenna Jack. Adjust the output of the signal generator for 0.2 Volts on the 2nd IF amplifier (position B on test set) and note the signal generator reading. Connect a 5600 ohm resistor between -10 Volts and the base of Q9 and increase signal generator until the same 2nd IF amplifier reading is obtained. Signal level must increase approximately 45 dB.</li><li>d. Check vehicle ignition system. Worn-out points, bad spark plugs, or breaks in ignition wiring can cause a "dirty" ignition pulse to be generated causing the blanker to operate incorrectly.</li></ol>

STEP 4—VOLTAGE RATIO READINGS

Equipment Required:

RF Voltmeter (similar to Boonton Model 91-CA or Millivac Type MV-18 C)

Procedure:

1. Apply probe to input of stage (for example, base of 1st RF Amp). Peak resonant circuit of stage being measured and take voltage reading ( $E_1$ ).
2. Move probe to input of following stage (2nd RF Amp). Repeak first resonant circuit. Then peak circuit being measured and take reading ( $E_2$ ).
3. Convert readings by means of the following formula.

$$\text{Voltage Ratio} = \frac{E_2}{E_1}$$

4. Check results with typical voltage ratios shown on diagram for each stage.

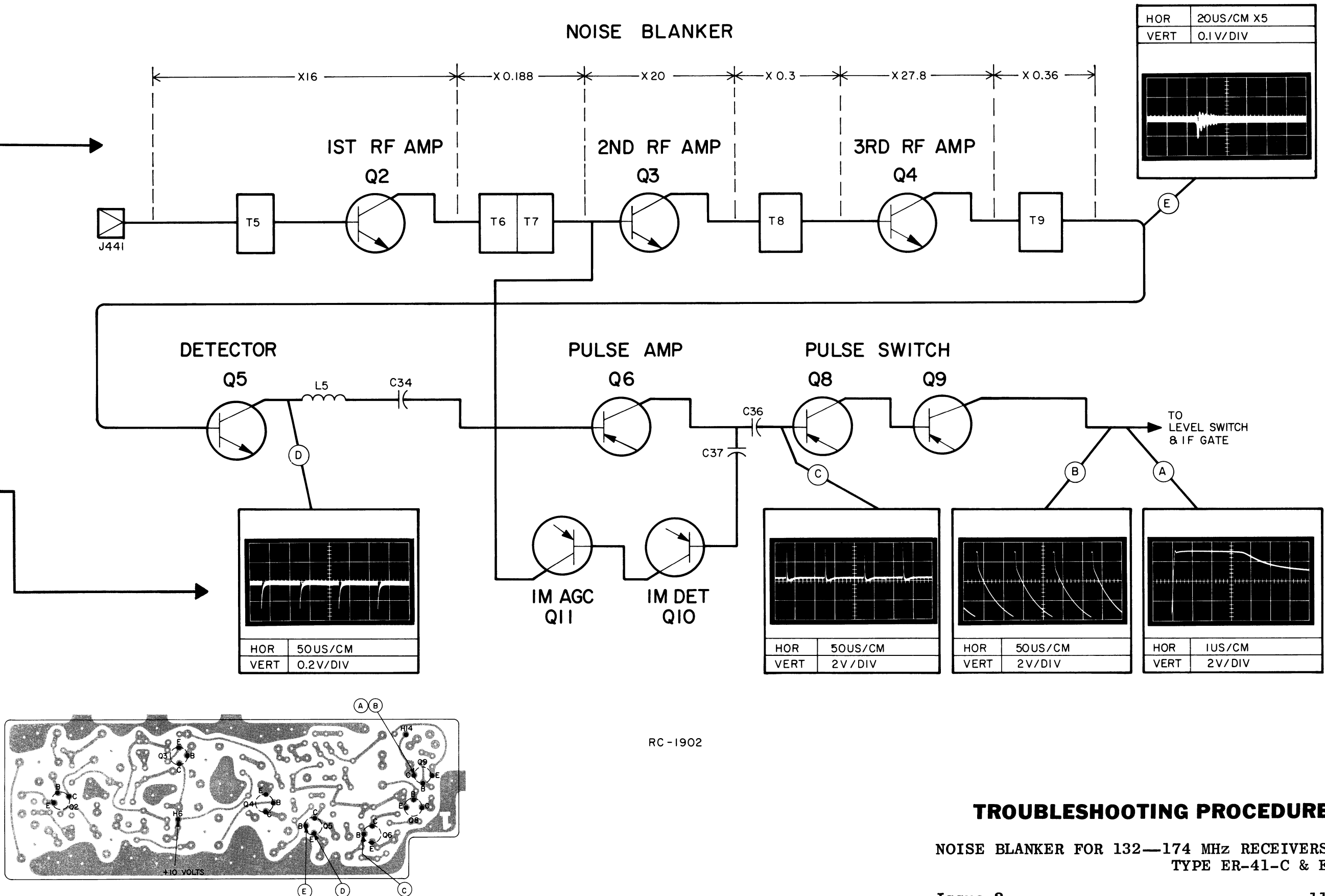
STEP 3—WAVE FORMS

Equipment Required:

Oscilloscope  
Pulse Generator (similar to General Electric Model 4EX4A10)

Procedure:

1. Set Pulse Generator to 10 kHz repetition rate and adjust for maximum output.
2. Observe waveforms on oscilloscope at points A through E. (scope settings are shown with the waveforms).



RC-1902

TROUBLESHOOTING PROCEDURE

NOISE BLANKER FOR 132—174 MHz RECEIVERS  
TYPE ER-41-C & E

STEP 1-QUICKCHECKS

TEST SET CHECKS

These checks are typical voltage readings measured with GE Test Set Model 4EX3A10 in the Test 1 position, or Model 4EX8K10 or 11 in the 1-volt position.

Metering Position	Reading with No Signal in	Reading with 1 μv unmodulated input
A Disc idling	Less than ±.05 VDC	
B 2nd IF	.05 VDC	0.2 VDC
C 1st Lim	0.6 VDC	0.8 VDC
D Mult 1	0.7 VDC	
E Mult 2	1 VDC	
J Regulated +10 Volts	10 VDC	

SYMPTOM CHECKS

SYMPTOM	PROCEDURE
NO SUPPLY VOLTAGE	• Check power connections and continuity of supply leads, and check fuse in power supply. If fuse is blown, check receiver for short circuits.
NO REGULATED 10-VOLTS	• Check the 12-volt supply. Then check regulator circuit (See Troubleshooting Procedure for Power Supply).
LOW 1ST LIM READING	• Check supply voltages and then check oscillator reading at J442-4 & 5 as shown in STEP 2A. • Make SIMPLIFIED VTVM GAIN CHECKS from 2nd Mixer through 1st Limiter stages as shown in STEP 2A.
LOW OSCILLATOR/MULTIPLIER READINGS	• Check alignment of Oscillator (Refer to Front End Alignment Procedure). • Check voltage and resistance readings of 1st Oscillator/Multiplier Q1/Q2. • Check crystal Y1.
LOW RECEIVER SENSITIVITY	• Check Front End Alignment (Refer to Receiver Alignment Procedure). • Check antenna connections, cable and relay. • Check 1st and 2nd Oscillator injection voltage. • Check voltage and resistance readings of 1st Mixer, HI IF Amp and 2nd Mixer. • Make SIMPLIFIED GAIN CHECKS (STEP 2A).
LOW AUDIO	• Check Audio PA (Q301 & Q302) voltage readings on schematic diagram. • Make simplified gain and waveform checks of audio and squelch stages (Steps 2A and 2B). • Make unsquelched voltage readings in Audio section (Refer to Receiver Schematic Diagram). • Check voltage and resistance readings on Channel Guard board.
HIGH DISTORTION AT LOW AUDIO LEVELS (50 MW)	• Set PA bias adjust R43 as specified under Service. • Checks in STEP 1 of TEST PROCEDURES.
IMPROPER SQUELCH OPERATION	• Check voltage and resistance readings of Squelch circuit (Refer to Receiver Schematic Diagram). • Make gain and waveform checks of audio and squelch stages (Steps 2A and 2B).
DISCRIMINATOR IDLING TOO FAR OFF ZERO	• See if discriminator zero is in center of IF bandpass.

STEP 3-VOLTAGE RATIO READINGS

EQUIPMENT REQUIRED:

- RF Voltmeter (Similiar to Boonton Model 91-CA or Millivac Type MV-18 C).

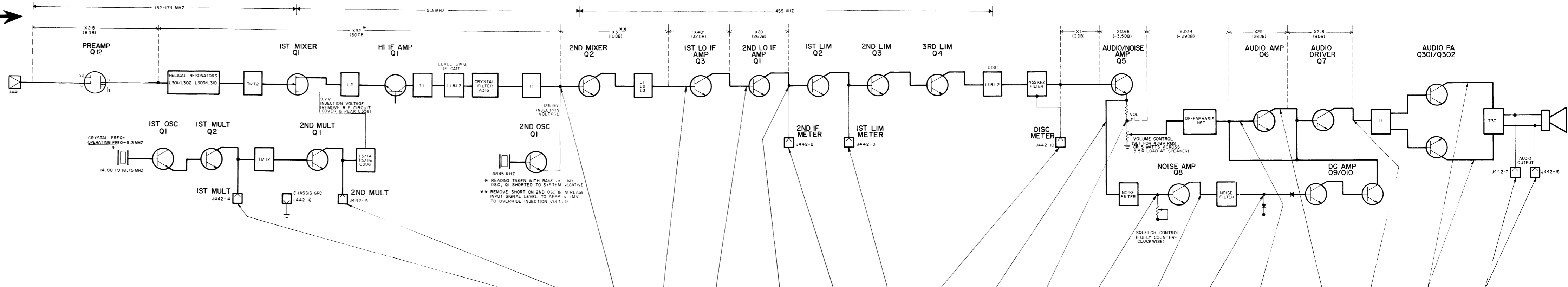
- Signal on receiver frequency (below saturation). Correct frequency can be determined by zeroing the discriminator. Use 1,000 Hertz signal with 3.0 kHz deviation for audio stage.

PROCEDURE

- Apply probes to input of stage and system negative (-10 VDC). Take voltage reading (E<sub>1</sub>).
- Move probes to input of following stage and system negative. Take reading (E<sub>2</sub>).
- Convert readings by means of the following formula:

$$\text{Voltage Ratio} = \frac{E_2}{E_1}$$

- Check results with typical voltage ratios shown on diagram.



STEP 2A-SIMPLIFIED VTVM GAIN CHECKS

EQUIPMENT REQUIRED:

- VTVM-AC & DC
- Signal Generator (measurements M560 or equiv.)

PRELIMINARY STEPS:

- Set VOLUME control for 4.18 volts across 3.5-ohm load. If this cannot be obtained, set to approx. 70% of max. rotation.
- Set SQUELCH control fully counterclockwise.
- Receiver should be properly aligned.
- Connect VTVM between system negative and points indicated by arrow (except for 1st and 2nd MULT which reference chassis ground).

SIGNAL GENERATOR INPUT AT J441 MAINTAIN SETTING AT DISCRIMINATOR ZERO			UNMODULATED	UNMODULATED	UNMODULATED	UNMODULATED	1 MICROVOLT UNMODULATED	NO SIGNAL INPUT	STANDARD SIGNAL- (1 MILLIVOLT AT RECEIVER MODULATED BY 1KHZ WITH 3.3KHZ DEVIATION)	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL
PROCEDURE			INCREASE GENERATOR OUTPUT UNTIL VTVM READING ON 10 V SCALE DECREASES BY 50 MV	INCREASE GENERATOR OUTPUT FROM ZERO UNTIL VTVM READING DECREASES BY 5%	INCREASE GENERATOR OUTPUT FROM ZERO UNTIL VTVM READING DECREASES BY 5%	INCREASE GENERATOR OUTPUT FROM ZERO UNTIL VTVM READING DECREASES BY 5%	INCREASE GENERATOR OUTPUT FROM ZERO UNTIL VTVM READING DECREASES BY 5%													CONNECT VTVM OR SCOPE ACROSS 3.5 OHM LOAD. J442-7 AND J442-15 WITH SPEAKER DISCONNECTED
READING	5 VDC GE TEST SET (POS D 0.7V)	2.5 VDC GE TEST SET (POS D 1.4V)	GENERATOR OUTPUT SHOULD BE APPROX 20 MILLIVOLTS	GENERATOR OUTPUT SHOULD BE APPROX 600 MICROVOLTS	GENERATOR OUTPUT SHOULD BE APPROX 5 MICROVOLTS	GENERATOR OUTPUT SHOULD BE APPROX 0.3 MICROVOLTS	-0.6 VDC GE TEST SET (POS B 0.3V)	- 2 VDC GE TEST SET (POS C 0.6V)	0.8 VAC	0.75 VAC	0.55 VAC	0.15 VAC	2.3 VAC	0.05 VAC		0.5 VAC	1.4 VAC	10 VAC	4.18 VAC	

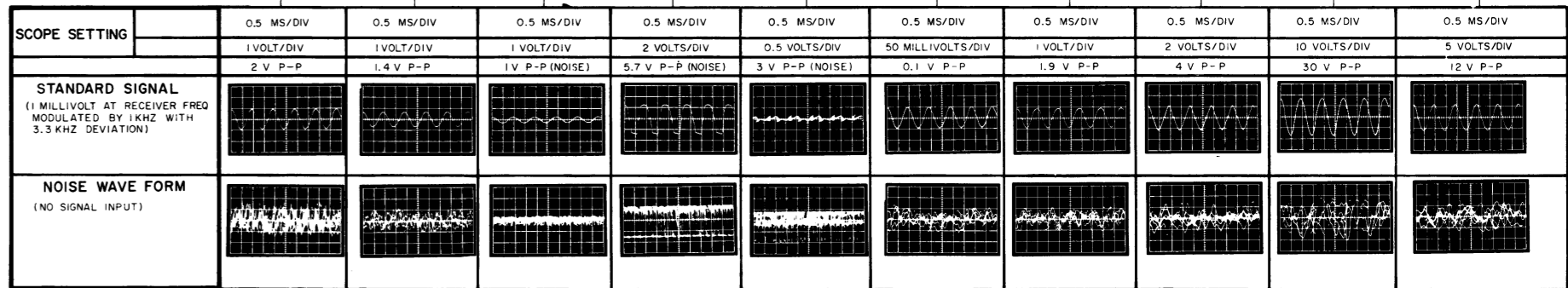
STEP 2B-AUDIO & SQUELCH WAVEFORMS

EQUIPMENT REQUIRED:

- Oscilloscope.
- Signal generator (measurements M560 to equivalent).

PRELIMINARY STEPS:

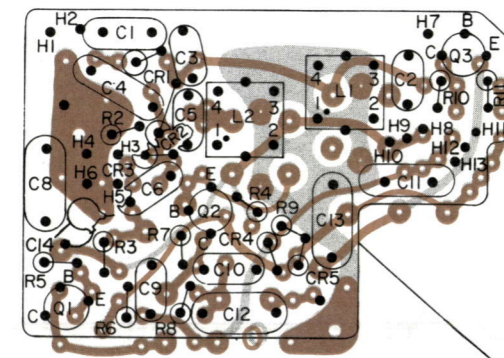
- Set VOLUME control for 4.18 volts across 3.5-ohm load. If this cannot be obtained, set to approx. 70% of max. rotation.
- Set SQUELCH control fully counterclockwise.
- Receiver should be properly aligned.
- Connect oscilloscope between system negative and points indicated by arrow.



TROUBLESHOOTING PROCEDURE

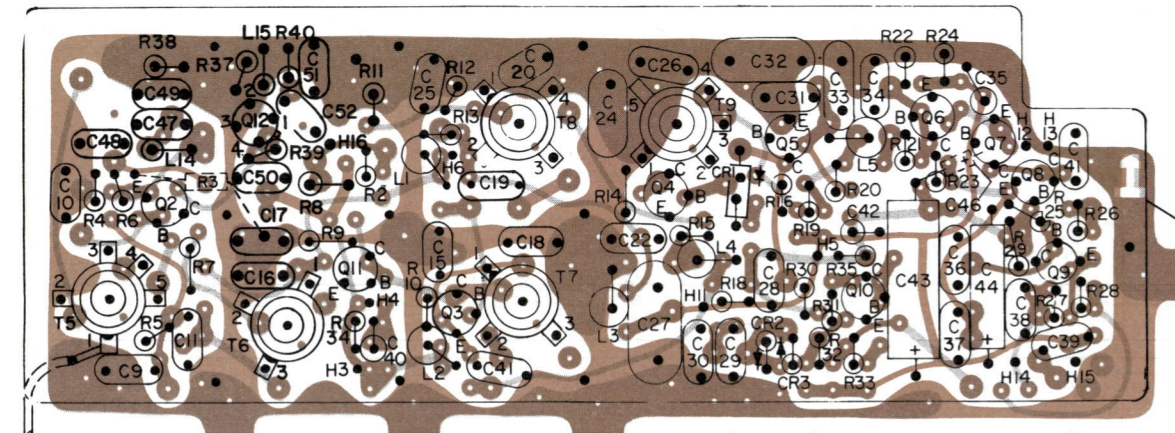
132—174 MHz MASTR RECEIVER  
MODELS 4ER41C22-33 & 4ER41E22-33

LEVEL SWITCH & IF GATE  
A325



NOISE BLANKER

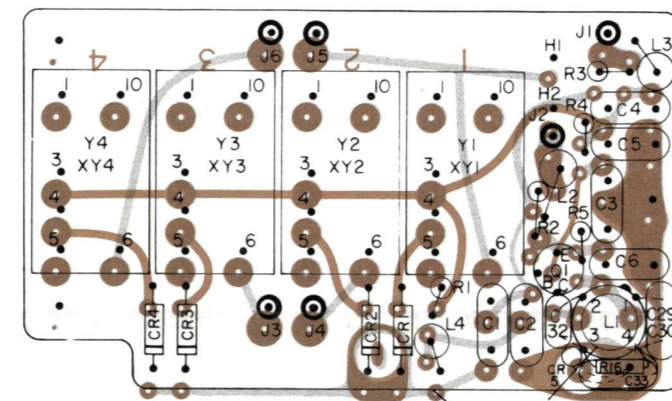
A323 - 132 - 150.8 MHZ  
A324 - 150.8 - 174 MHZ



(19B216558, Sh. 1, Rev. 1)  
(19B216558, Sh. 2, Rev. 1)

IST OSC/MULT (WITH ICOM)

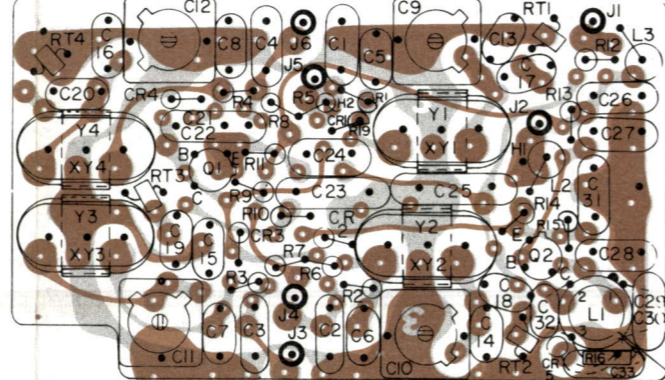
	<u>132-150.8 MHZ</u>	<u>150.8-174 MHZ</u>
I-FREQ	A311	A313
MULTI-FREQ -	A312	A314



(19B216155, Sh. 1, Rev. 0)  
(19B216155, Sh. 2, Rev. 0)

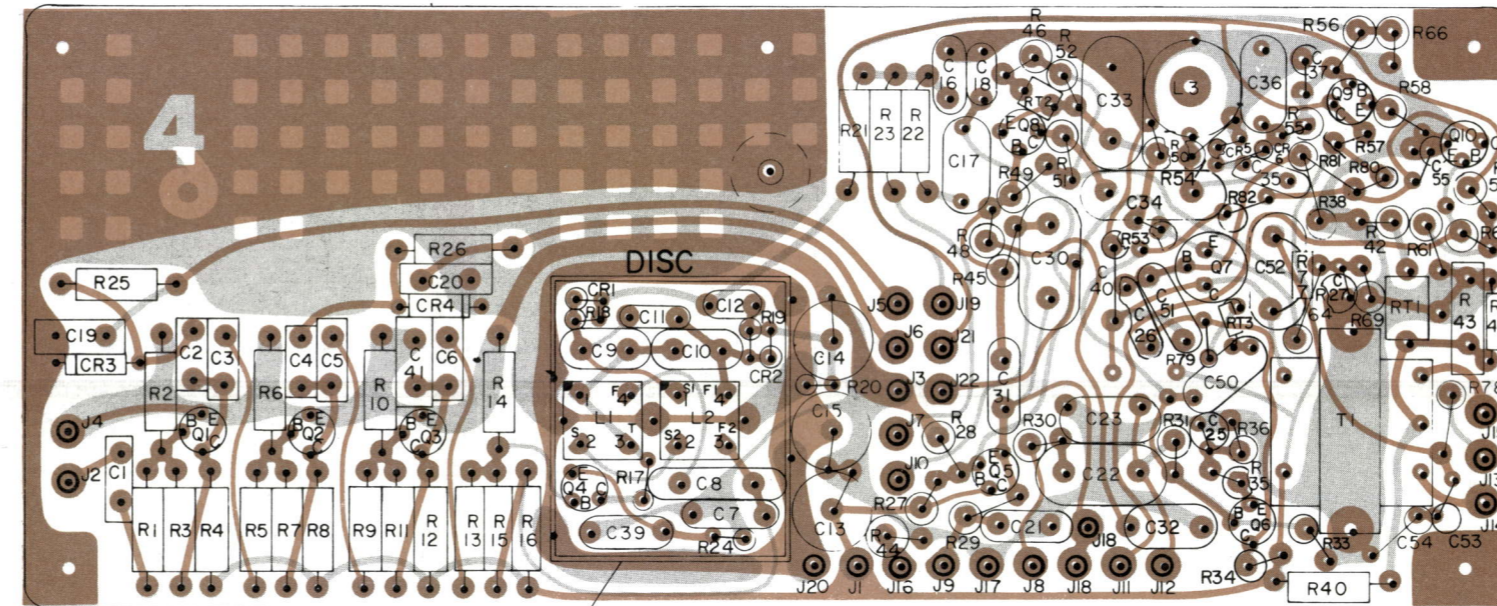
## 1ST OSCILLATOR

	132-150.8 MHz	150.8-174 MHz
1-FREQ	A305	A306
2-FREQ	A307	A308
4-FREQ	A309	A310



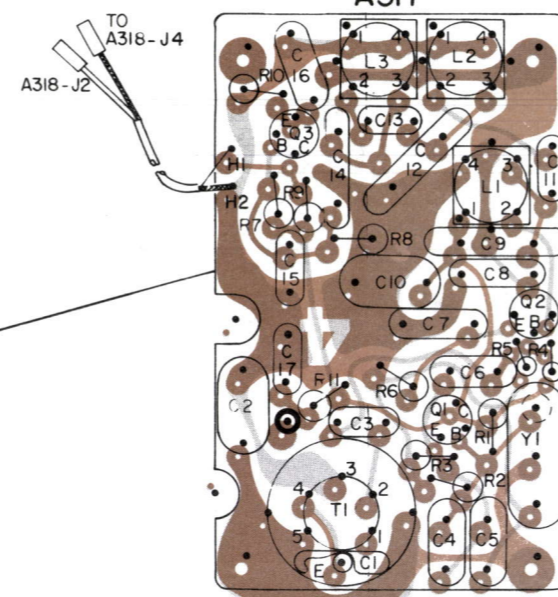
(19B204412, Sh. 1, Rev. 3)  
(19B204412, Sh. 2, Rev. 3)

IF-AUDIO & SQUELCH BOARD  
A318

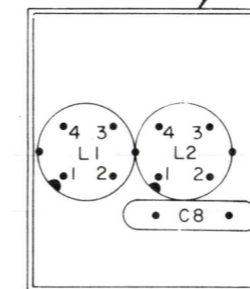


(19C311803, Sh. 1, Rev. 4)  
(19C311803, Sh. 2, Rev. 6)

2ND MIXER  
A317



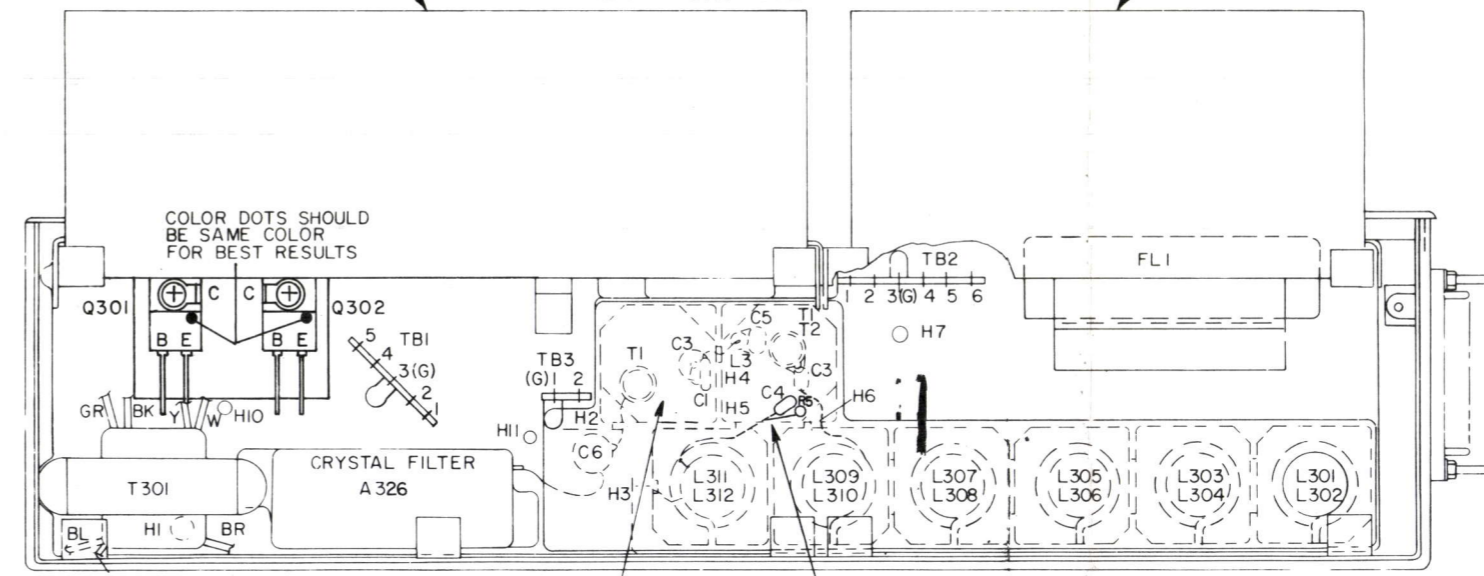
(19B216045, Sh. 1, Rev. 4)  
(19B216045, Sh. 2, Rev. 3)



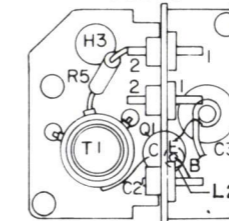
ALTERNATE LI & L

PIN NUMBER MARKING  
ON SIDE OF COIL CAN  
OR COLOR DOT IDENTI-  
FIES PIN NUMBER 1 OF  
DISCRIMINATOR AND  
2ND MIXER COILS.

BOTTOM VIEW

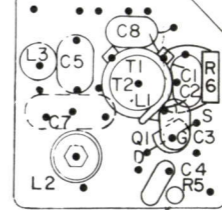


HI IF AMP  
A315

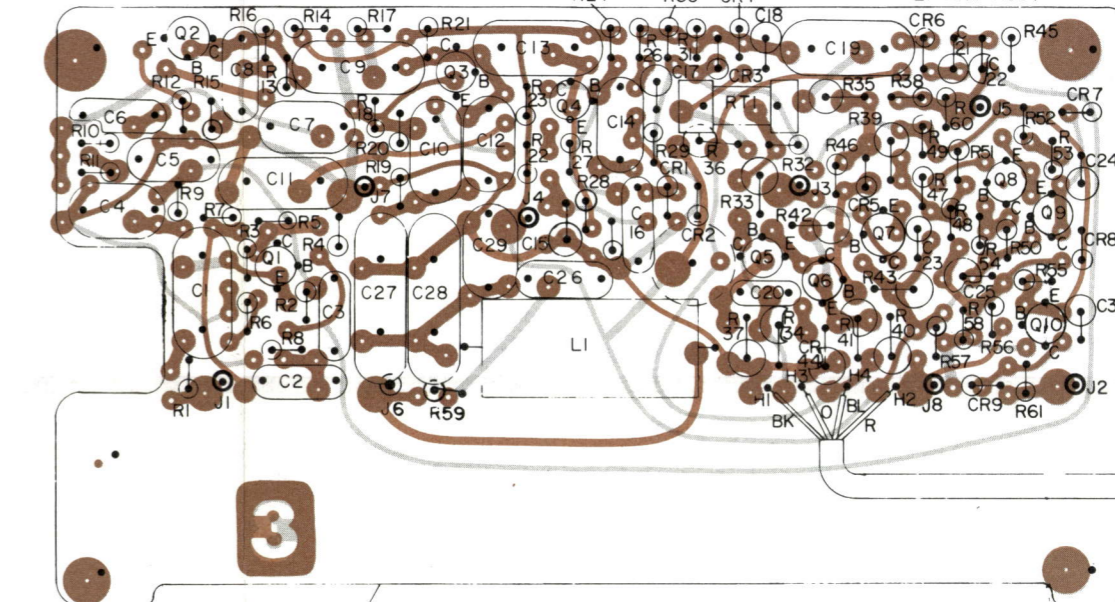


**1ST MIXER**  
A301 (132-150.8MHz)  
A302 (150.8-174MHz)

A502 (150.0) (74 MHz)



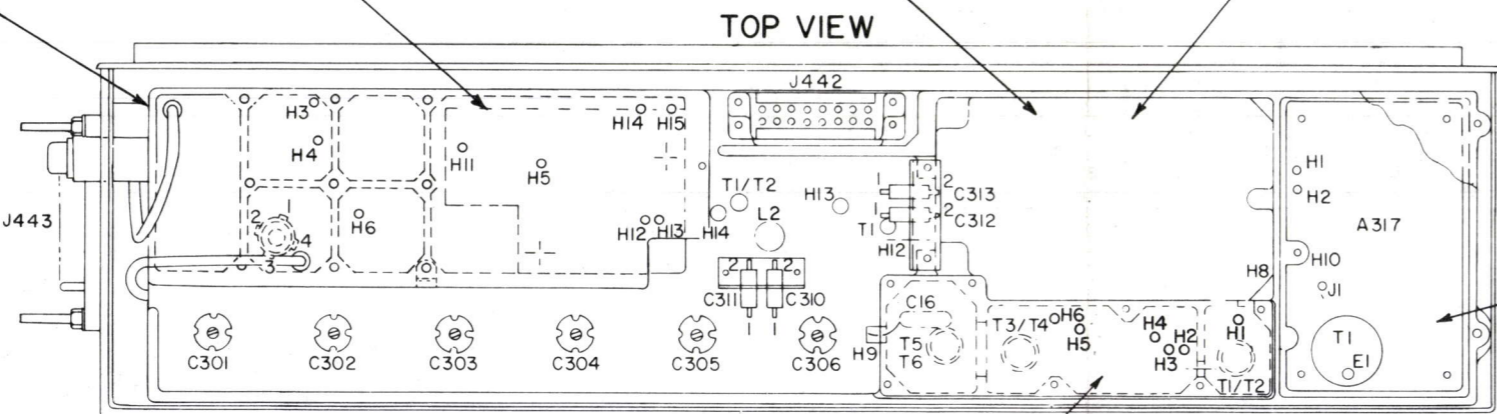
ENCODER-DECODER  
A319



(19C311794, Sh. 1, Rev. 3)  
(19C311794, Sh. 2, Rev. 3)

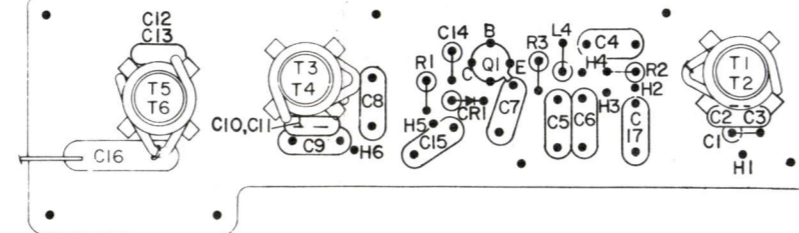
**TONE REJECT FILTER**  
A320 (CONSISTS OF  
R30 CR4 LI AND R59)

0 (CONSISTS OF C26 THRU C29,  
LI AND R59)

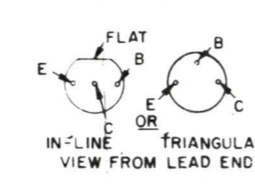


2ND MULTIPLIER

A303 (132-150.8 MHz)  
A304 (150.8-174 MHz)



### TRANSISTOR LEAD IDENTIFICATION



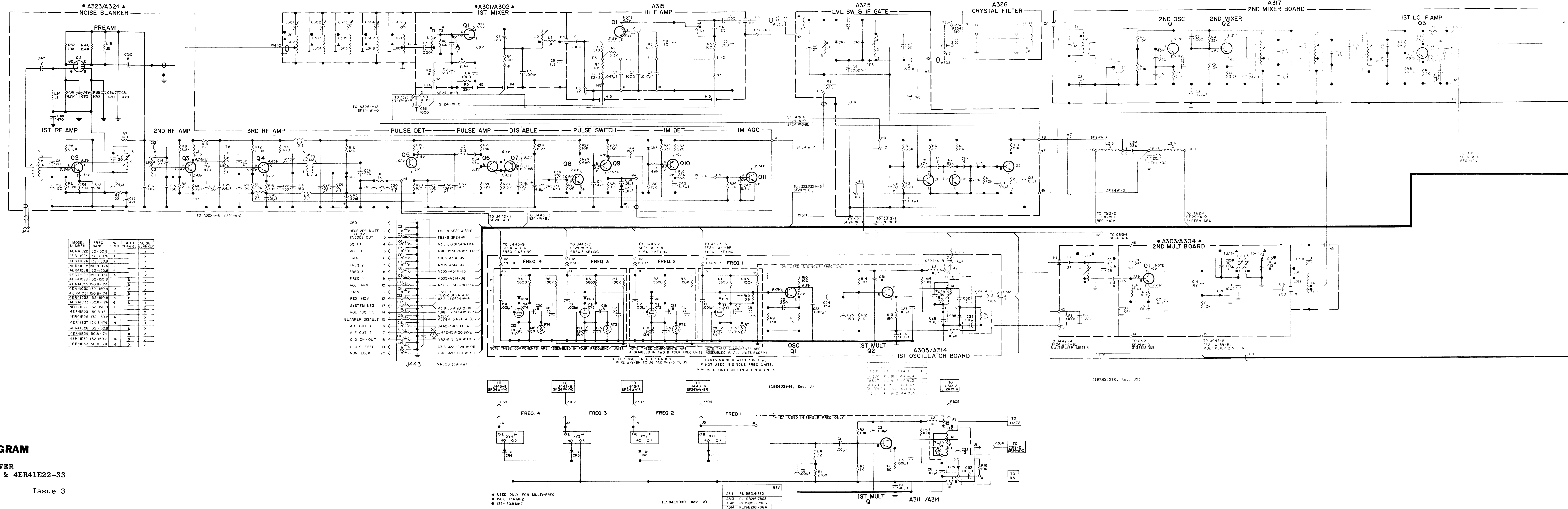
NOTE: LEAD ARRANGEMENT, AND NOT CASE SHAPE, IS DETERMINING FACTOR FOR LEAD IDENTIFICATION

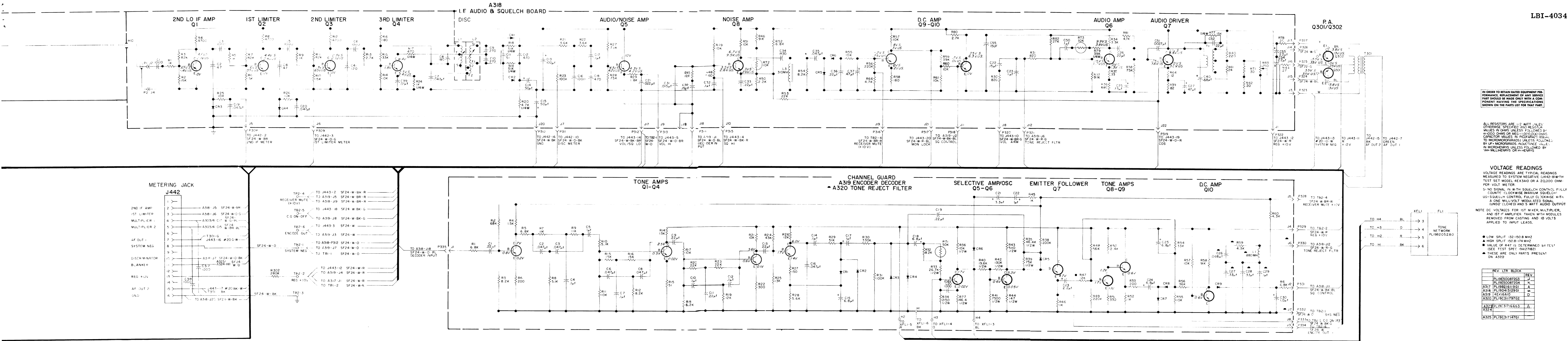
(19R621322, Rev. 18)



### SCHEMATIC DIAGRAM

132-174 MHz RECEIVER  
MODELS 4ER41C22-33 & 4ER41E22-33





IN ORDER TO RETAIN RATED EQUIPMENT PERFORMANCE, REPLACEMENT OF ANY SERVICE PART SHOULD BE MADE ONLY WITH A COMPONENT HAVING THE SPECIFICATIONS SHOWN ON THE PARTS LIST FOR THAT PART.

ALL RESISTORS ARE 1/2 WATT UNLESS OTHERWISE SPECIFIED AND RESISTOR VALUES IN OHMS UNLESS FOLLOWED BY K=1000 OHMS OR MEG=1,000,000 OHMS. CAPACITOR VALUES IN MICROFARADS (EQ. TO MICROFARADS) UNLESS FOLLOWED BY P=PICTOFARADS, N=NEPOMER, OR M=MICROHENRYS UNLESS FOLLOWED BY M= MILLIHENRYS OR H=HENRYS.

**VOLTAGE READINGS**  
VOLTAGE READINGS ARE TYPICAL READINGS MEASURED TO SYSTEM NEGATIVE (J442-BW) WITH TEST SET MODEL 4EX3A10 OR A 20,000 OHM PER VOLT METER.  
S: NO SIGNAL IN WITH SQUELCH CONTROL FULLY COUNTER CLOCKWISE MAXIMUM SQUELCH.  
US: SQUELCH CONTROL FULLY CLOCKWISE WITH A ONE MILLIVOLT MODULATED SIGNAL (UNSCLOCHED) AND 5 WATT AUDIO OUTPUT.  
NOTE: DC VOLTAGES FOR 1ST METER, MULTIPLIER, AND 1ST IF AMPLIFIER TAKEN WITH MODULES REMOVED FROM CASTING AND 10 VOLTS APPLIED TO INPUT LEADS.

- LOW SPLIT 132-150.8 MHZ
- ▲ HIGH SPLIT 150.8-174 MHZ
- VALUE OF R47 IS DETERMINED BY TEST (SEE TEST SPEC 9A27282)
- ▲ THESE ARE ONLY PARTS PRESENT ON A320

REV.	LTR.	BLOCK
PL19E50087203	J	
PL19E50087204	K	
A317	PL19B216119G1	A
A318	PL19B413129G1	M
A319	4E16A10	D
A320	PL19C311797G2	
A321	PL19C311797G2	
A322	PL19C311797G2	
A323	PL19C311797G2	
A324	PL19C311797G2	
A325	PL19C311797G2	

## SCHEMATIC DIAGRAM

132—174 MHz RECEIVER  
MODELS 4ER41C22-33 & 4ER41E22-33

SYMBOL	G-E PART NO	DESCRIPTION	SYMBOL	G-E PART NO	DESCRIPTION	SYMBOL	G-E PART NO	DESCRIPTION	SYMBOL	G-E PART NO	DESCRIPTION	SYMBOL	G-E PART NO	DESCRIPTION	SYMBOL	G-E PART NO	DESCRIPTION	SYMBOL	G-E PART NO	DESCRIPTION	SYMBOL	G-E PART NO	DESCRIPTION	SYMBOL	G-E PART NO	DESCRIPTION	SYMBOL	G-E PART NO	DESCRIPTION			
C4	5496219P717	Ceramic disc: 47 pf ±10%, 500 VDCW, temp coef -750 PPM.	C50	19A116080P7	Polyester: 0.1 μf ±20%, 50 VDCW.	R17	3R152P471J	Composition: 470 ohms ±5%, 1/4 w.	R64*	3R77P120J	Composition: 12 ohms ±5%, 1/2 w.	C19	19A116080P109	Polyester: 0.22 μf ±10%, 50 VDCW.	G9 and Q10	19A115123P1	Silicon, NPN; sim to Type 2N2712.	R47C	3R77P103J	Composition: 10,000 ohms ±5%, 1/2 w.	C13	5491601P23	Phenolic: 1.5 pf ±10%, 500 VDCW.									
C5 and C6	5494481P111	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.	C51	19A116655P22	Ceramic disc: 2700 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.	R18 and R19	3R152P513J	Composition: 51,000 ohms ±5%, 1/4 w.		3R77P180J	Composition: 18 ohms ±5%, 1/2 w.	C20	5494481P111	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.				R47D	3R77P113J	Composition: 11,000 ohms ±5%, 1/2 w.	C15	5496203P341	Ceramic disc: 150 pf ±10%, 500 VDCW, temp coef -4700 PPM.									
C7	19A116080P5	Polyester: 0.047 μf ±20%, 50 VDCW.	C52	19A116080P109	Polyester: 0.22 μf ±10%, 50 VDCW.	R20	3R152P472K	Composition: 4700 ohms ±10%, 1/4 w.	R66	3R77P472K	Composition: 4700 ohms ±10%, 1/2 w.	C21	5496267P9	Tantalum: 3.3 μf ±20%, 15 VDCW; sim to Sprague Type JF Discap.	R1	3R77P682K	Composition: 6800 ohms ±10%, 1/2 w.	R47E	3R77P123J	Composition: 12,000 ohms ±5%, 1/2 w.	C16	19A116080P1	Polyester: 0.01 μf ±20%, 50 VDCW.									
C8	19A116656P180J1	Ceramic disc: 180 pf ±5%, 500 VDCW, temp coef -150 PPM.	C53 and C54	5496267P213	Tantalum: 0.2 μf ±20%, 20 VDCW; sim to Sprague Type 150D.	R21 and R22	3R77P362J	Composition: 3600 ohms ±5%, 1/2 w.	R75*	3R77P473J	Composition: 47,000 ohms ±5%, 1/2 w. Deleted by REV C.	C22	5496267P17	Tantalum: 1.0 μf ±20%, 35 VDCW; sim to Sprague Type 150D.	R2	3R77P683J	Composition: 68,000 ohms ±5%, 1/2 w.	R47F	3R77P133J	Composition: 13,000 ohms ±5%, 1/2 w.	C17	19A116655P13	Ceramic disc: 470 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.									
C9 and C10	5490008P37	Silver mica: 270 pf ±5%, 500 VDCW; sim to Electro Motive Type DM-15.	C55*	5496267P14	Tantalum: 15 μf ±20%, 20 VDCW; sim to Sprague Type 150D. Added by REV C.	R23	3R77P104K	Composition: 0.1 megohms ±10%, 1/2 w.	R76*	3R77P912J	Composition: 9100 ohms ±5%, 1/2 w. Deleted by REV C.	C23	5496267P13	Tantalum: 2.2 μf ±20%, 20 VDCW; sim to Sprague Type 150D.	R3	3R77P682J	Composition: 8200 ohms ±5%, 1/2 w.	R47H	3R77P752J	Composition: 7500 ohms ±5%, 1/2 w.	C18	5496203P341	Ceramic disc: 150 pf ±10%, 500 VDCW, temp coef -4700 PPM.									
C11	5496219P656	Ceramic disc: 51 pf ±5%, 500 VDCW, temp coef -470 PPM.			----- DIODES AND RECTIFIERS -----	R24	3R152P102J	Composition: 1000 ohms ±5%, 1/4 w.	R77*	3R152P153J	Composition: 15,000 ohms ±5%, 1/4 w.	C24	5496267P1	Tantalum: 6.8 μf ±20%, 6 VDCW; sim to Sprague Type 150D.	R4	3R77P152J	Composition: 1500 ohms ±5%, 1/2 w.	R48	3R77P563J	Composition: 56,000 ohms ±5%, 1/2 w.	C19	19A116655P13	Ceramic disc: 470 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.									
C12	5494481P108	Ceramic disc: 470 pf ±10%, 1000 VDCW; sim to RMC Type JF Discap.	CR1 and CR2	19A115250P1	Silicon.	R25 and R26	3R77P103K	Composition: 10,000 ohms ±10%, 1/2 w.		3R152P562J	Composition: 5600 ohms ±5%, 1/4 w.	C25	5496267P18	Tantalum: 6.8 μf ±20%, 35 VDCW; sim to Sprague Type 150D.	R5	3R77P682K	Composition: 6800 ohms ±10%, 1/2 w.	R50	3R77P242J	Composition: 2400 ohms ±5%, 1/2 w.	C22	5496203P341	Ceramic disc: 150 pf ±10%, 500 VDCW, temp coef -4700 PPM.									
C13	19A115680P107	Electrolytic: 100 μf +150% -10%, 15 VDCW; sim to Mallory Type TT.	CR3* and CR4*	19A115250P1	Silicon.	R27 and R28	3R77P753J	Composition: 75,000 ohms ±5%, 1/2 w.	R78*	3R77P200J	Composition: 20 ohms ±5%, 1/2 w.	C26	19A116080P206	Polyester: 0.068 μf ±5%, 50 VDCW.	R6	3R77P201J	Composition: 200 ohms ±5%, 1/2 w.	R51	3R77P331J	Composition: 330 ohms ±5%, 1/2 w.	C25	19A116080P1	Polyester: 0.01 μf ±20%, 50 VDCW.									
C14 and C15	19A115680P104	Electrolytic: 50 μf +150% -10%, 25 VDCW; sim to Mallory Type TT.			In REV F and earlier:	R29	3R77P182J	Composition: 1800 ohms ±5%, 1/2 w.		3R77P100J	Composition: 10 ohms ±5%, 1/2 w.	C27 and C28	19A116080P210	Polyester: 0.33 μf ±5%, 50 VDCW.	R7	19A116278P305	Metal film: 11,000 ohms ±2%, 1/2 w.	R52	3R77P331J	Composition: 330 ohms ±5%, 1/2 w.	C26	19A116080P107	Polyester: 0.1 μf ±10%, 50 VDCW.									
C16	5494481P112	Ceramic disc: 1000 pf ±10%, 500 VDCW; sim to RMC Type JF Discap.	CR5 and CR6	4038056P1	Germanium.	R30*	3R77P821J	Composition: 820 ohms ±5%, 1/2 w.	R79	3R152P393J	Composition: 39,000 ohms ±5%, 1/4 w.				C29	19A116080P205	Polyester: 0.047 μf ±5%, 50 VDCW.	R8	3R77P562J	Composition: 5600 ohms ±5%, 1/2 w.	C28	19A116655P13	Ceramic disc: 470 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.									
C17	19A116080P7	Polyester: 0.1 μf ±20%, 50 VDCW.			Silicon.		3R77P102J	Composition: 1000 ohms ±5%, 1/2 w.	R80*	3R152P272J	Composition: 2700 ohms ±5%, 1/4 w.				C30	5496267P17	Tantalum: 1.0 μf ±20%, 35 VDCW; sim to Sprague Type 150D.	R9	19A116278P305	Metal film: 11,000 ohms ±2%, 1/2 w.	C29	5496218P6	Ceramic disc: 6.0 pf ±0.5 pf, 500 VDCW, temp coef 0 PPM.									
C18	5494481P108	Ceramic disc: 470 pf ±10%, 1000 VDCW; sim to RMC Type JF Discap.	CR7* and CR8*	19A115250P1	Silicon. Deleted by REV C.	R31	3R77P821J	Composition: 820 ohms ±5%, 1/2 w.		3R152P432J	Composition: 4300 ohms ±5%, 1/4 w. Added by REV C.	CR1 and CR2	19A115250P1	Silicon.	R10	3R77P512J	Composition: 5100 ohms ±5%, 1/2 w.	R13	3R77P153J	Composition: 15,000 ohms ±5%, 1/2 w.	R53	3R77P201J	Composition: 200 ohms ±5%, 1/2 w.									
C19 and C20	19A116080P5	Polyester: 0.047 μf ±20%, 50 VDCW.			----- JACKS AND RECEPTACLES -----	R32	3R77P912J	Composition: 9100 ohms ±5%, 1/2 w.	R81*	3R152P472J	Composition: 4700 ohms ±5%, 1/4 w. Added by REV C.	CR3 and CR4	5494922P1	Silicon.	R11	3R77P103J	Composition: 10,000 ohms ±5%, 1/2 w.	R14	3R77P133J	Composition: 13,000 ohms ±5%, 1/2 w.	R54	3R77P333J	Composition: 33,000 ohms ±5%, 1/2 w.	C27	19A116080P7	Polyester: 0.1 μf ±20%, 50 VDCW.						
C21	19A116080P3	Polyester: 0.022 μf ±20%, 50 VDCW.	J1 thru J22	4033513P4	Contact, electrical: sim to Bead Chain L93-3.	R33	3R77P330K	Composition: 33 ohms ±10%, 1/2 w.	R82*	3R77P723J	Composition: 27,000 ohms ±5%, 1/2 w. Added by REV C.				R12	3R77P822J	Composition: 8200 ohms ±5%, 1/2 w.	R15	3R77P510J	Composition: 51 ohms ±5%, 1/2 w.	R55	3R77P103J	Composition: 10,000 ohms ±5%, 1/2 w.	C28	19A116655P13	Ceramic disc: 470 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.						
C22	19A116080P108	Polyester: 0.15 μf ±10%, 50 VDCW.	L1	19A115711P6	Transformer, freq: 455 KHz; sim to TOKO PEFCN-14733-CX12.	R34	3R77P332K	Composition: 3300 ohms ±10%, 1/2 w.	R85*	3R152P102J	Composition: 1000 ohms ±5%, 1/4 w. Added by REV K. Deleted by REV L.	CR5	19A115250P1	Silicon.	R13	3R77P153J	Composition: 15,000 ohms ±5%, 1/2 w.	R16	3R77P153J	Composition: 15,000 ohms ±5%, 1/2 w.	R56	3R77P363J	Composition: 36,000 ohms ±5%, 1/2 w.	C29	5496218P6	Ceramic disc: 6.0 pf ±0.5 pf, 500 VDCW, temp coef 0 PPM.						
C23	19A116080P107	Polyester: 0.1 μf ±10%, 50 VDCW.	L2	19A115711P7	Transformer, freq: 455 KHz; sim to TOKO PEFCN-14734-BNL2.	R35	3R77P330K	Composition: 33 ohms ±10%, 1/2 w.			----- THERMISTORS -----	CR6	4036887P1	Silicon, Zener.	R14	3R77P133J	Composition: 13,000 ohms ±5%, 1/2 w.	R17	3R77P103J	Composition: 10,000 ohms ±5%, 1/2 w.	R57	3R77P103K	Composition: 10,000 ohms ±10%, 1/2 w.									
C25	5496267P6	Tantalum: 33 μf ±20%, 10 VDCW; sim to Sprague Type 150D.	L3	19A127134G1	Choke. Includes tuning slug 7486872P7.	R36	3R77P681J	Composition: 680 ohms ±5%, 1/2 w.	RT1	5490828P41	Thermistor: 30 ohms ±10%, color code black, white; sim to Globar Type BL11H-4.	CR7 thru CR9	19A115250P1	Silicon.	R15	3R77P103J	Composition: 10,000 ohms ±5%, 1/2 w.	R18	3R77P622J	Composition: 6200 ohms ±5%, 1/2 w.	R58	3R77P913J	Composition: 91,000 ohms ±5%, 1/2 w.	C30 and C31	19A116655P19	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.						
C26*	19A116080P109	Polyester: 0.22 μf ±10%, 50 VDCW.			In REV H and earlier:	R37	3R77P241J	Composition: 240 ohms ±5%, 1/2 w.	RT2 and RT3	5490828P9	Thermistor: 10,000 ohms ±10%, color code yellow; sim to Globar Type 551H8.				R16	3R77P153J	Composition: 15,000 ohms ±5%, 1/2 w.	R19	3R77P123J	Composition: 12,000 ohms ±5%, 1/2 w.	R59*	3R77P182J	Polyester: 0.047 μf ±20%, 50 VDCW.	C32	19A116080P5	Polyester: 0.047 μf ±20%, 50 VDCW.						
	5496267P28	Tantalum: 0.47 μf ±20%, 35 VDCW; sim to Sprague Type 150D.	Q1 thru Q6	19A115123P1	Silicon, NPN; sim to Type 2N2712.	R38	3R77P752J	Composition: 7500 ohms ±5%, 1/2 w.			----- TRANSFORMERS -----	FL1			R17	3R77P103J	Composition: 10,000 ohms ±5%, 1/2 w.	R20	3R77P223J	Composition: 22,000 ohms ±5%, 1/2 w.	R60	3R77P432J	Composition: 4300 ohms ±5%, 1/2 w.	C33	5496218P17	Ceramic disc: 47 pf ±10%, 500 VDCW, temp coef 0 PPM.						
C27*	5496267P2	Tantalum: 47 μf ±20%, 6 VDCW; sim to Sprague Type 150D.	Q7	19A115300P4	Silicon, NPN; sim to Type 2N3053.	R39	3R77P820J	Composition: 82 ohms ±5%, 1/2 w.	T1	19A116040P1	Audio freq: 300-4000 Hz, Pri: 18.3 ohms ±10% DC res, Sec: 23.5 ohms ±10% DC res.				R18	3R77P622J	Composition: 6200 ohms ±5%, 1/2 w.	R21	3R77P103J	Composition: 10,000 ohms ±5%, 1/2 w.	R61	3R77P432J	Composition: 4300 ohms ±5%, 1/2 w.	C34	19A116655P13	Ceramic disc: 470 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.						
	5496267P6	Tantalum: 33 μf ±20%, 10 VDCW; sim to Sprague Type 150D.	Q8	19A115123P1	Silicon, NPN; sim to Type 2N2712.	R40*	3R77P221J	Composition: 220 ohms ±5%, 1/2 w.	A319	19A116040P1	Encoder/Decoder 4EK16A10 19C311797G1				R19	3R77P123J	Composition: 12,000 ohms ±5%, 1/2 w.	R22	3R77P301J	Composition: 300 ohms ±5%, 1/2 w.												
C30	19A116080P8	Polyester: 0.15 μf ±20%, 50 VDCW.	Q9	19A115362P1	Silicon, NPN; sim to Type 2N2925.	R41	3R152P240J	Composition: 24 ohms ±5%, 1/4 w.			----- CAPACITORS -----				R20	3R77P223J	Composition: 22,000 ohms ±5%, 1/2 w.	R23	3R77P223J	Composition: 22,000 ohms ±5%, 1/2 w.	C35	5496267P1	Tantalum: 6.8 μf ±20%, 6 VDCW; sim to Sprague Type 150D.									
C31	19A116080P102	Polyester: 0.015 μf ±10%, 50 VDCW.	Q10*	19A116774P1	Silicon, NPN; sim to Type 2N5210.	R42	3R77P200J	Composition: 20 ohms ±5%, 1/2 w.			----- TRANSFORMERS -----				R21	3R77P103J	Composition: 10,000 ohms ±5%, 1/2 w.	R24	3R77P433J	Composition: 43,000 ohms ±5%, 1/2 w.	C40	5496267P1	Tantalum: 6.8 μf ±20%, 6 VDCW; sim to Sprague Type 150D.									
C32	19A116080P7	Polyester: 0.1 μf ±20%, 50 VDCW.			In REV G and earlier:	R43	19B209358P101	Variable, carbon film: approx 25 to 250 ohms ±10%, 0.2 w; sim to CTS Type X-201.			----- CAPACITORS -----				R22	3R77P301J	Composition: 300 ohms ±5%, 1/2 w.	R25	3R77P133J	Composition: 13,000 ohms ±5%, 1/2 w.	C41	19A116655P13	Ceramic disc: 470 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.									
C33	19A116080P9	Polyester: 0.22 μf ±20%, 50 VDCW.			Silicon, NPN; sim to Type 2N2712.	R44	19B209022P101	Wirewound: .27 ohms ±10%, 2 w; sim to IRC Type BWH.			----- CAPACITORS -----				R23	3R77P223J	Composition: 22,000 ohms ±5%, 1/2 w.	R26	3R77P123J	Composition: 12,000 ohms ±5%, 1/2 w.	C42	5496267P9	Tantalum: 3.3 μf ±20%, 15 VDCW; sim to Sprague Type 150D.									
C34	4029003P207	Silver mica: 1830 pf ±2%, 500 VDCW; sim to Electro Motive Type DM-20.			----- RESISTORS -----	R45	3R77P123J	Composition: 12,000 ohms ±5%, 1/2 w.			----- CAPACITORS -----				R24	3R77P433J	Composition: 43,000 ohms ±5%, 1/2 w.	R27	3R77P151J	Composition: 150 ohms ±5%, 1/2 w.	C43	19A115680P3	Electrolytic: 20 μf +150% -10%, 25 VDCW; sim to Mallory Type TT.									
C35	19A116080P5	Polyester: 0.047 μf ±20%, 50 VDCW.	R1	3R77P102K	Composition: 1000 ohms ±10%, 1/2 w.	R46	3R77P913J	Composition: 91,000 ohms ±5%, 1/2 w.			----- CAPACITORS -----				R25	3R77P133J	Composition: 13,000 ohms ±5%, 1/2 w.	R28	3R77P562J	Composition: 5600 ohms ±5%, 1/2 w.	C44	5496267P14	Tantalum: 15 μf ±20%, 20 VDCW; sim to Sprague Type 150D.									
C36*	19A116080P9	Polyester: 0.22 μf ±20%, 50 VDCW.	R2	3R77P153J	Composition: 15,000 ohms ±5%, 1/2 w.	R47	19A116278P249	Metal film: 3160 ohms ±2%, 1/2 w.			----- CAPACITORS -----				R26	3R77P151J	Composition: 150 ohms ±5%, 1/2 w.	R29	3R77P513J	Composition: 51,000 ohms ±5%, 1/2 w.	C45	19A116080P1	Polyester: 0.01 μf ±20%, 50 VDCW.									
	19B209243P7	Polyester: 0.1 μf ±20%, 50 VDCW.	R3	3R77P823K	Composition: 82,000 ohms ±10%, 1/2 w.	R48	3R77P103J	Composition: 10,000 ohms ±5%, 1/2 w.			----- CAPACITORS -----				R27	3R77P151J	Composition: 150 ohms ±5%, 1/2 w.	R30	3R77P562J	Composition: 5600 ohms ±5%, 1/2 w.	C46	5496267P9	Polyester: 0.068 μf ±5%, 50 VDCW.									
C37	5496267P28	Tantalum: 0.47 μf ±20%, 35 VDCW; sim to Sprague Type 150D.	R4	3R77P472K	Composition: 4700 ohms ±10%, 1/2 w.	R49	3R77P103J	Composition: 10,000 ohms ±5%, 1/2 w.			----- CAPACITORS -----				R28	3R77P103J	Composition: 10,000 ohms ±5%, 1/2 w.	R31	3R77P104J	Composition: 0.1 megohm ±5%, 1/2 w.	C47	19A116656P10A1	Ceramic disc: 710 pf ±5%, 500 VDCW, temp coef -750 PPM.									
C38*	5496267P1	Tantalum: 15 μf ±20%, 15 VDCW; sim to Sprague Type 150D. Deleted by REV C.	R5	3R77P102K	Composition: 1000 ohms ±10%, 1/2 w.	R50	3R77P222J	Composition: 2200 ohms ±5%, 1/2 w.			----- CAPACITORS -----				R29	3R77P151J	Composition: 150 ohms ±5%, 1/2 w.	R32	3R77P822J	Composition: 8200 ohms ±5%, 1/2 w.	C48	19A116655P14	Ceramic disc: 470 pf ±10%, 1000 VDCW; sim to RMC Type JF Discap.									
C39	19A116080P1	Polyester: 0.01 μf ±20%, 50 VDCW.	R6	3R77P153J	Composition: 15,000 ohms ±5%, 1/2 w.	R51	3R77P102J	Composition: 10,000 ohms ±5%, 1/2 w.			----- CAPACITORS -----				R30	3R77P334J	Composition: 33,000 ohms ±5%, 1/2 w.	R33	19A116278P342													

4ER4IC10-33  
4ER4IE10-45

PRODUCTION CHANGES

Changes in the equipment to improve performance or to simplify circuits are identified by a "Revision Letter", which is stamped after the number of the assembly. The revision stamped on the assembly includes all previous revisions. Refer to the Parts List for descriptions of parts affected by these revisions.

- REV. A - (19E500872G3 & G4) CHASSIS AND RF CIRCUIT

To eliminate squelch opening thump in receivers with Channel Guard. Remove white-orange wire between J443-13 and TB2-1. Added a white-orange wire between J512 (on J17 on IF Audio and Squelch board) and TB2-1. Added C46, C14 and R304. Deleted R12. Changed C2 and TB3.

**NOISE BLANKER A324**

To assure band-end tuning at 150.8 MHz. Changed C2.

**LEVEL SWITCH/IF GATE A325**

To improve level switch operation. Changed R12.

**TROUBLESHOOTING PROCEDURE CHANGE (PAGE 11)**

In Step 2 - Quick Checks, changed procedure "C".

Procedure was:

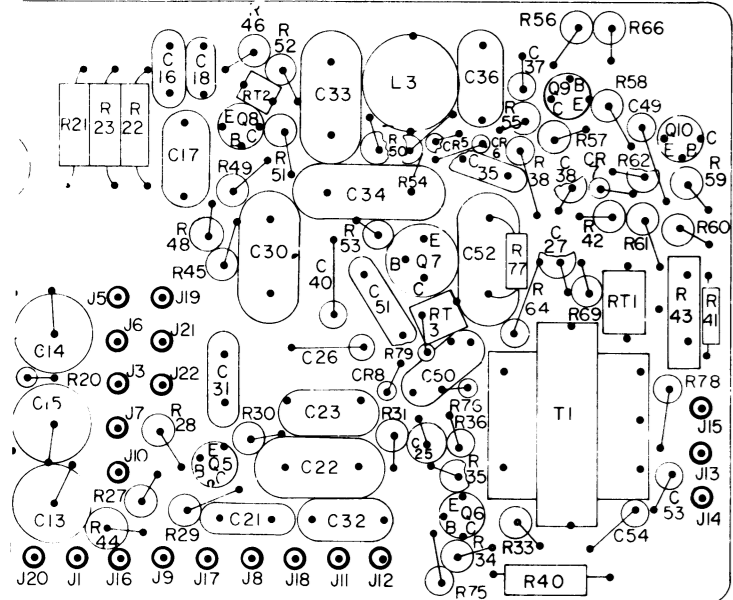
C. Check IF Gate as follows:  
Connect signal generator to Antenna Jack. Adjust the output of the signal generator for 0.2 volts on the 2nd IF amplifier (position B on test set) and note the signal generator reading. Connect a 5600 ohm resistor between +10 volts and R14 and increase signal generator until the same 2nd IF amplifier reading is obtained. Signal level must increase approximately 45 db.
- REV. B - (19D413129G1) IF AUDIO & SQUELCH BOARD A318

To more precisely control the squelch control rotation. Changed R46.
- REV. C - (19D413129G1) IF AUDIO & SQUELCH BOARD A318

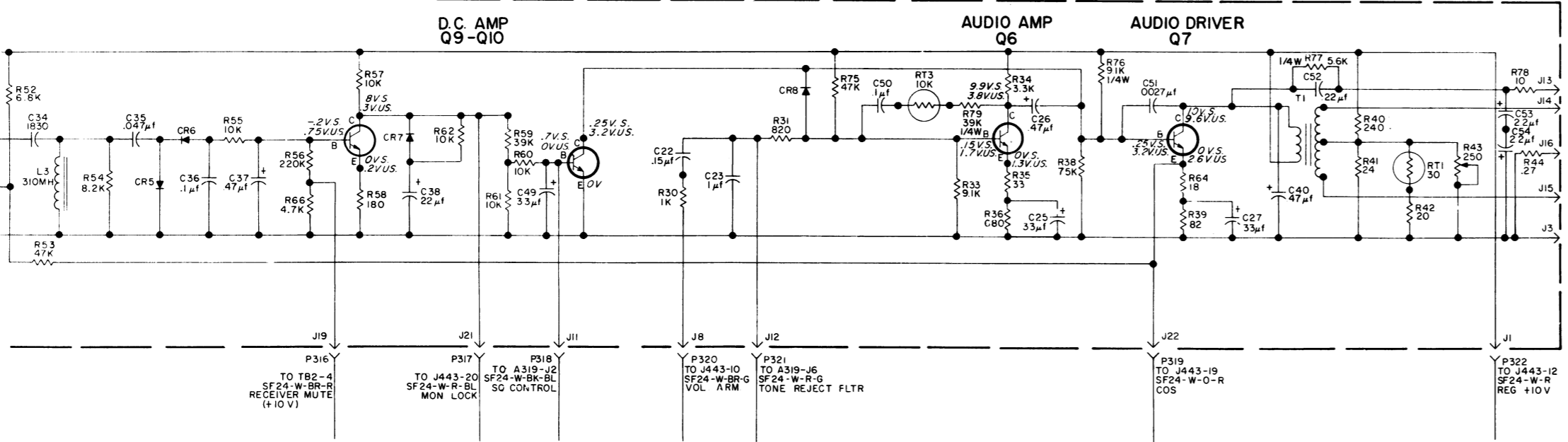
To eliminate barely audible squelch switching transients and to reduce receiver squelch tail. Deleted C38, C49, CR7, C38, R62, R75 and R16.

Outline Diagram Was:

IF-AUDIO & SQUELCH BOARD A318



Schematic Diagram Was:



- REV. E - (19E500872G3) CHASSIS AND RF CIRCUIT

To prevent oscillations in the Hi-IF Amplifier (A315). Added L2 (ferrite bead).
- REV. F - (19E500872G4) CHASSIS AND RF CIRCUIT

To stabilize the 1st Mixer. Deleted R301 on the 2nd Multiplier and added R5 to the 1st Mixer.
- REV. G - (19E500872G3) CHASSIS AND RF CIRCUIT

To lower the input impedance of the 1st Mixer and eliminate oscillation. Added R6.
- REV. C - (19E500872G4) CHASSIS AND RF CIRCUIT

To improve tuning of the 1st Mixer. Changed C2.
- REV. D - (19E500872G3) CHASSIS AND RF CIRCUIT

To eliminate Thyrector. Deleted CR1.
- REV. D - (19E500872G4) CHASSIS AND RF CIRCUIT

To eliminate Thyrector. Deleted CR1.
- REV. D - (19E500872G3) CHASSIS AND RF CIRCUIT

To lower the input impedance of the 1st Mixer and eliminate oscillation. Add R6.
- REV. H - (19E500872G4) CHASSIS AND RF CIRCUIT

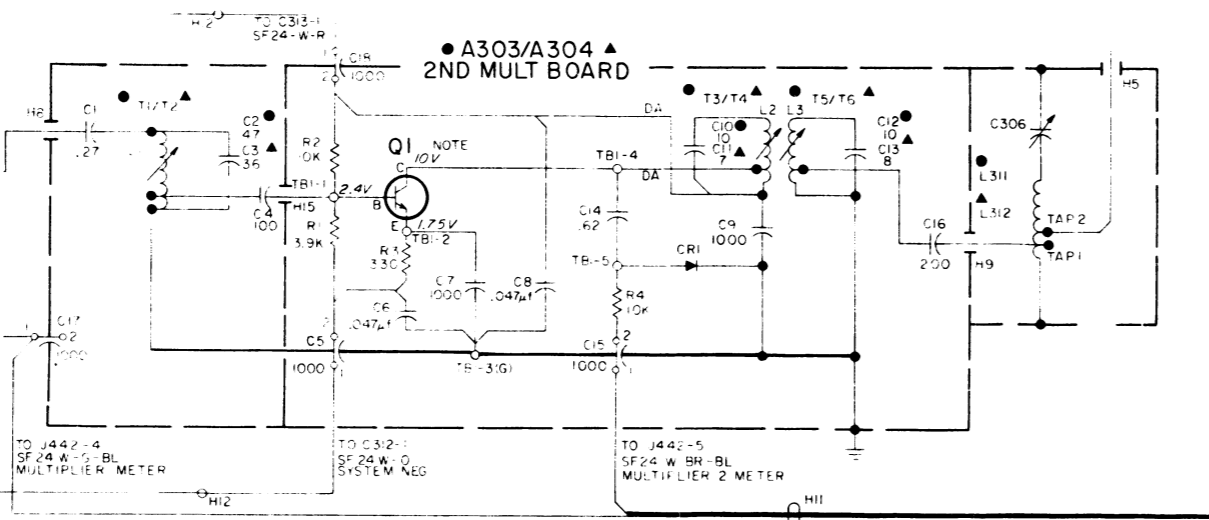
To incorporate a new-transistor. Changed Q301 and Q302.
- REV. H - (19E500872G3) CHASSIS AND RF CIRCUIT

To incorporate a new-transistor. Changed Q301 and Q302.
- REV. J - (19E500872G4) CHASSIS AND RF CIRCUIT

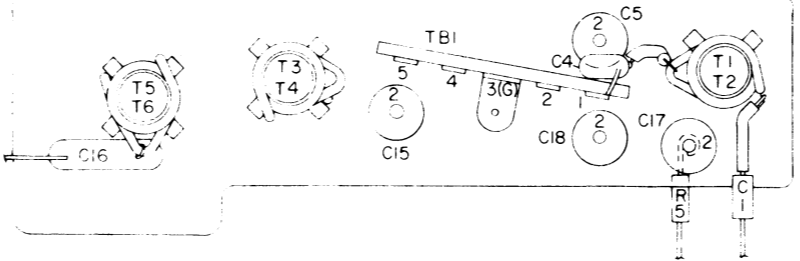
To lower the input impedance of the 1st Mixer and eliminate oscillation. Add R6.
- REV. J - (19E500872G3) CHASSIS AND RF CIRCUIT

To incorporate improved design. Changed 2nd Mult Board (A303/A304).

Schematic Diagram was:



2ND MULTIPLIER  
A303 (132-150.8 MHZ)  
A304 (150.8-174 MHZ)

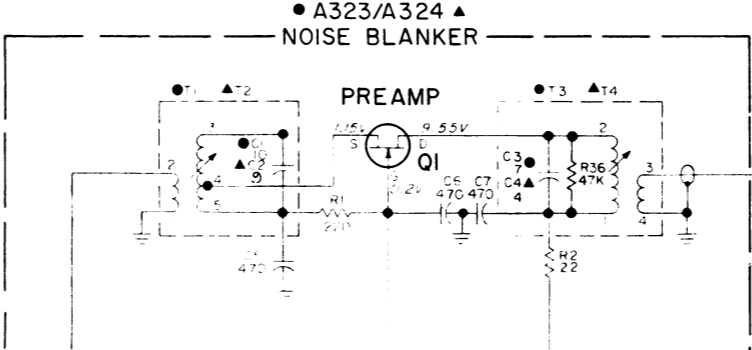


- REV. J - (19E500872G3) CHASSIS AND RF CIRCUIT

To incorporate an improved Noise Blanker board (A323 A324). Changed A323 A324 from 19C317166G1,G2 to a 19C317166G3 assembly.
- REV. K - (19E500872G4) CHASSIS AND RF CIRCUIT

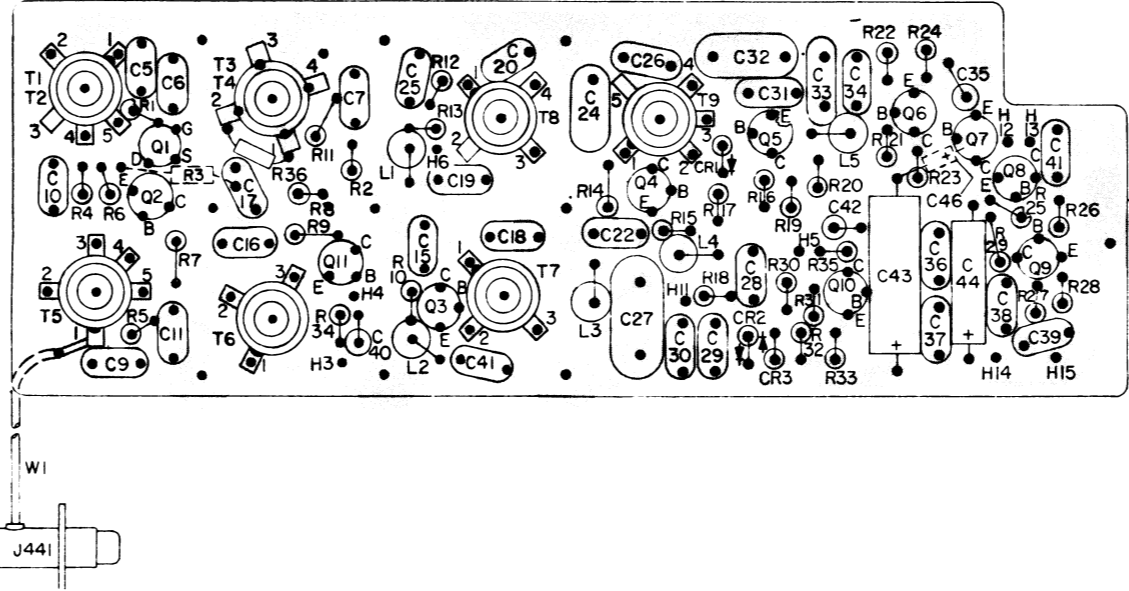
To incorporate an improved Noise Blanker board (A323 A324). Changed A323 A324 from 19C317166G1,G2 to a 19C317166G3 assembly.

Schematic Diagram was:



Outline Diagram was:

NOISE BLANKER  
A323 - 132-150.8 MHZ  
A324 - 150.8-174 MHZ



The following revision letter changes have been made to improve receiver performance and to facilitate production. The revision stamped on the assemblies includes all previous revisions.

**CHASSIS AND RF CIRCUIT 19E500872-G3 & G4**

Rev. A - To eliminate squelch opening thump in receivers with Channel Guard. Removed white-orange wire between J443-13 and TB2-1. Added a white-orange wire between P312 (or J17 on IF Audio and Squelch board) and TB2-1.

**NOISE BLANKER A324 (19C317166-G2)**

Rev. A - To assure band-end tuning at 150.8 MHz. Changed C2 from 5496218-P638 (7 pF) to 5496218-P640 (9 pF).

**LEVEL SWITCH/IF GATE A325 (19C317147-G1)**

Rev. A - To improve level switch operation. Changed R12 from 3R77-P472K (4.7K ohms) to 3R77-P332K (3.3K ohms).

**TROUBLESHOOTING PROCEDURE CHANGE (PAGE 11)**

In Step 2 - Quick Checks, Change Procedure "C" to read as follows:

SYMPTOMS	PROCEDURE
Partial or no blanking	c. Check IF Gate as follows: Connect signal generator to Antenna Jack. Adjust the output of the signal generator for 0.2 volts on the 2nd IF amplifier (position B on test set) and note the signal generator reading. Connect a 5600 ohm resistor between -10 Volts and the base of Q9 and increase signal generator until the same 2nd IF amplifier reading is obtained. Signal level must increase approximately 45 dB.

**IF AUDIO & SQUELCH BOARD A318 (19D413129-G1)**

Rev. B - To control more closely the squelch control rotation. Changed R48 from 3R77-P332J (3300 ohms  $\pm 5\%$ ) to 19A116278-P249 (3160 ohms  $\pm 2\%$ ).

Rev. C - To eliminate barely audible squelch switching transients and to reduce receiver squelch tail.

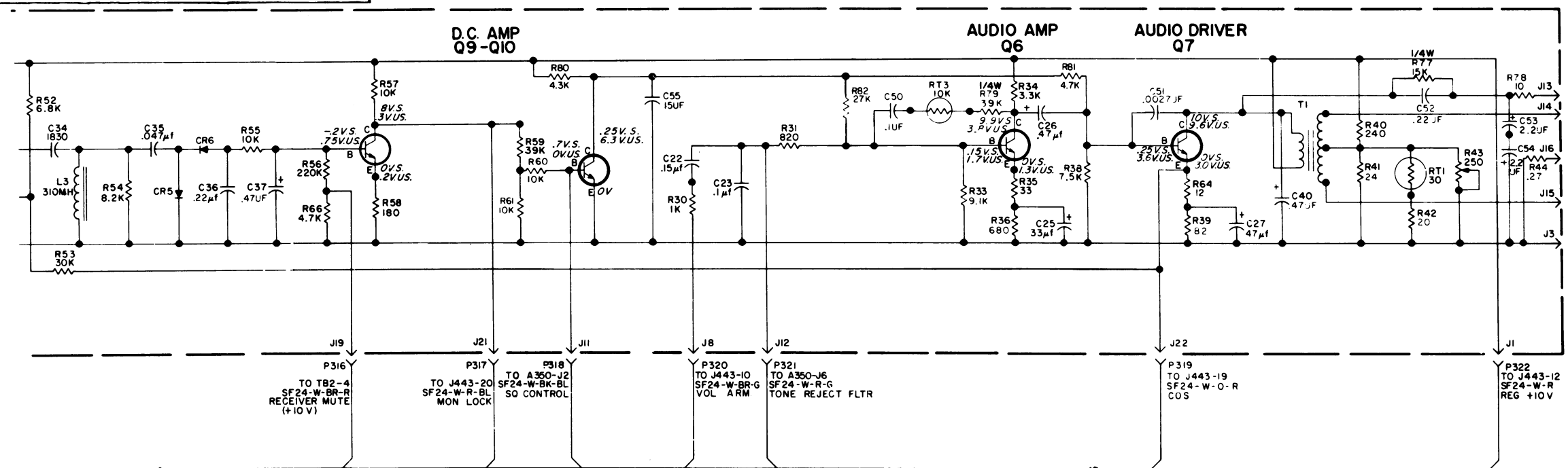
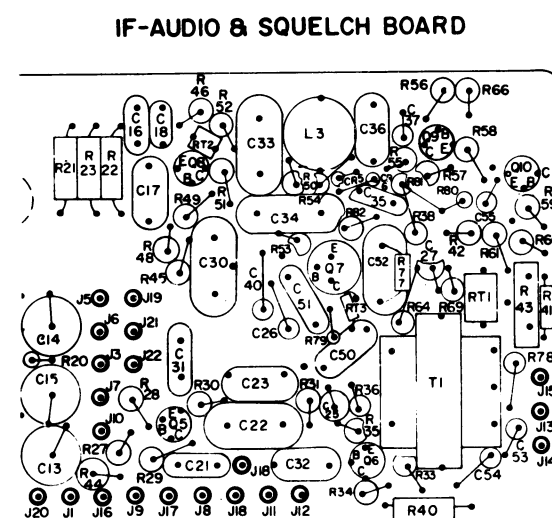
DELETED: C38, C49, CR7, CR8, R62, R75 and R76

ADDED: C55 (5496267-P14, 15  $\mu$ F)  
R80 (3R152-P432J, 4.3K ohms  $\pm 5\%$ )  
R81 (3R152-P472J, 4.7K ohms  $\pm 5\%$ )  
R82 (3R77-P273J, 27K ohms  $\pm 5\%$ )

CHANGED	FROM	TO
C27	5496267-P6 (33 $\mu$ F)	5496267-P2 (47 $\mu$ F)
C36	19B209243-P7 (0.1 $\mu$ F)	19B209243-P17 (0.22 $\mu$ F)
R53	3R77-P473 (47K ohms)	3R77-P303J (30K ohms)
R64	3R77-P180J (18 ohms)	3R77-P120J (12 ohms)
R77	3R152-P562J (5.6K ohms)	3R152-P153J (15K ohms)

Schematic Diagram Changed To:

Outline Diagram Changed To:





## ORDERING SERVICE PARTS

Each component appearing on the schematic diagram is identified by a symbol number, to simplify locating it in the parts list. Each component is listed by symbol number, followed by its description and GE Part Number.

Service parts may be obtained from Authorized GE Communication Equipment Service Stations or through any GE Radio Communication Equipment Sales Office. When ordering a part, be sure to give:

1. GE Part Number for component
2. Description of part
3. Model number of equipment
4. Revision letter stamped on unit

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These instructions do not purport to cover all details or variations in equipment nor to provide for every possible contingency to be met in connection with the installation, operation or maintenance.

Should further information be desired, or should particular problems arise which are not covered sufficiently for the purchaser's purposes, contact the nearest Radio Communication Equipment Sales Office of the General Electric Company.

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**MAINTENANCE MANUAL**

**LBI-4034**

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**MOBILE RADIO DEPARTMENT**  
**GENERAL ELECTRIC COMPANY • LYNCHBURG, VIRGINIA 24502**



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